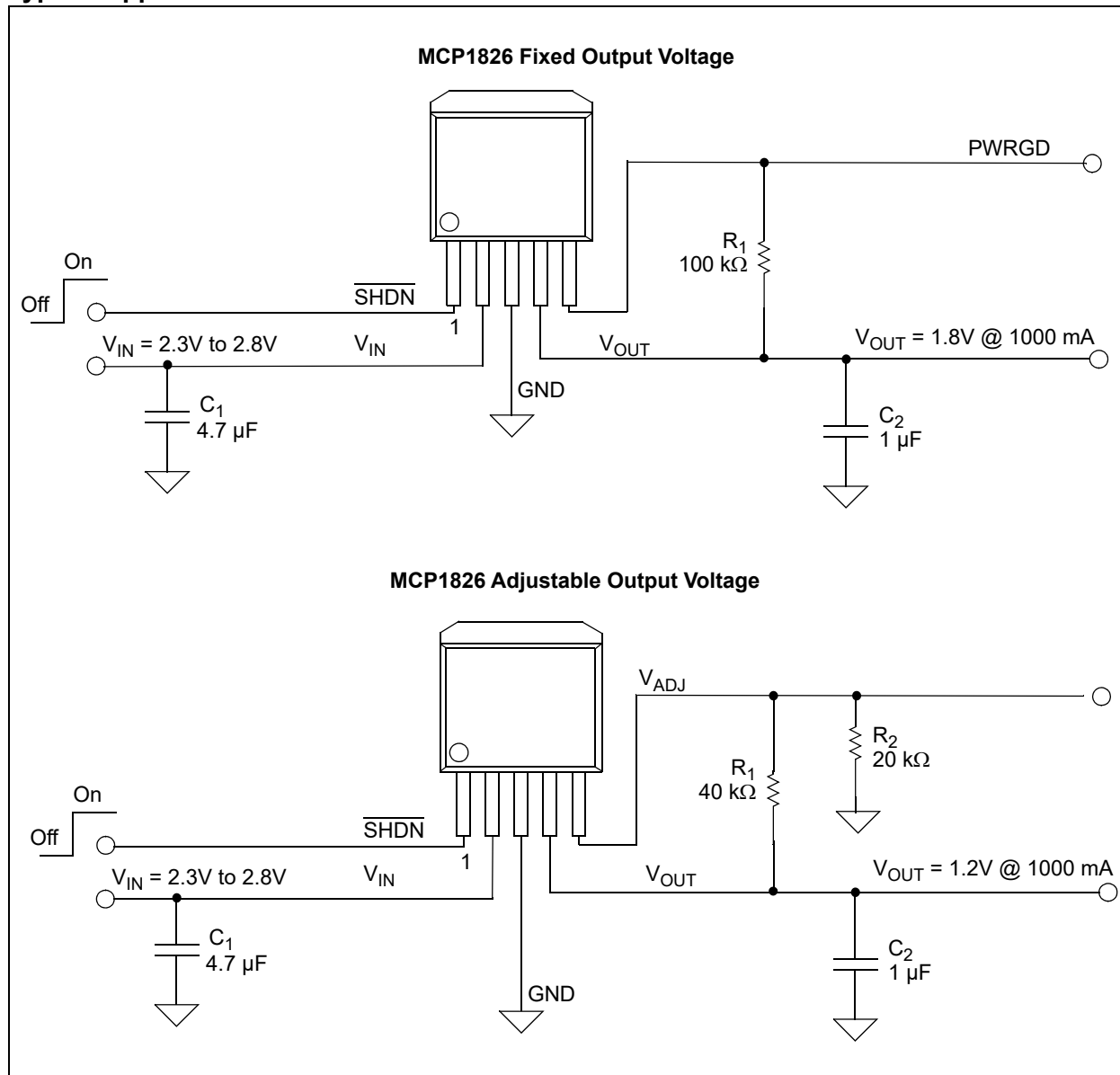


Package Types

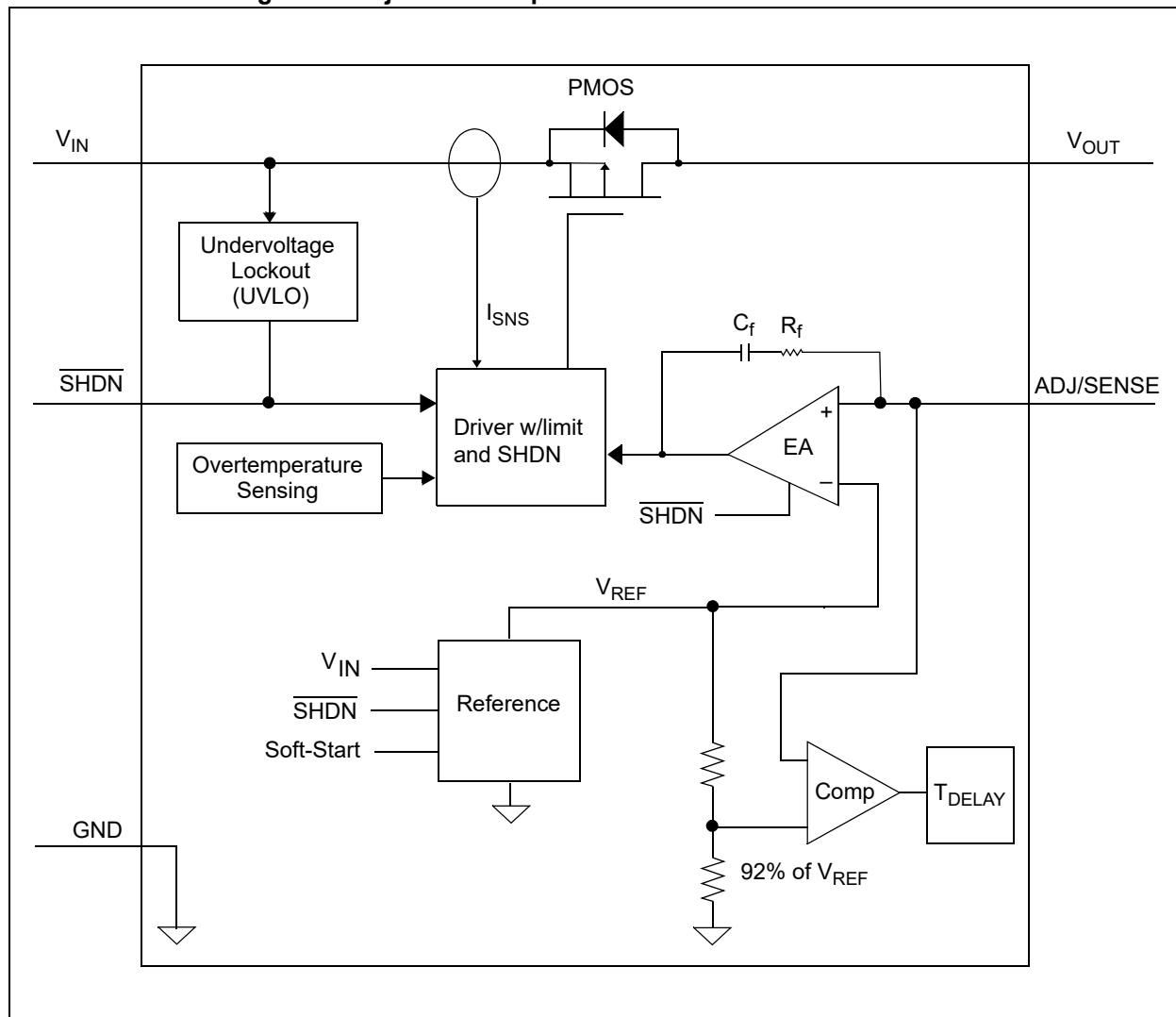
MCP1826/MCP1826S

Typical Application

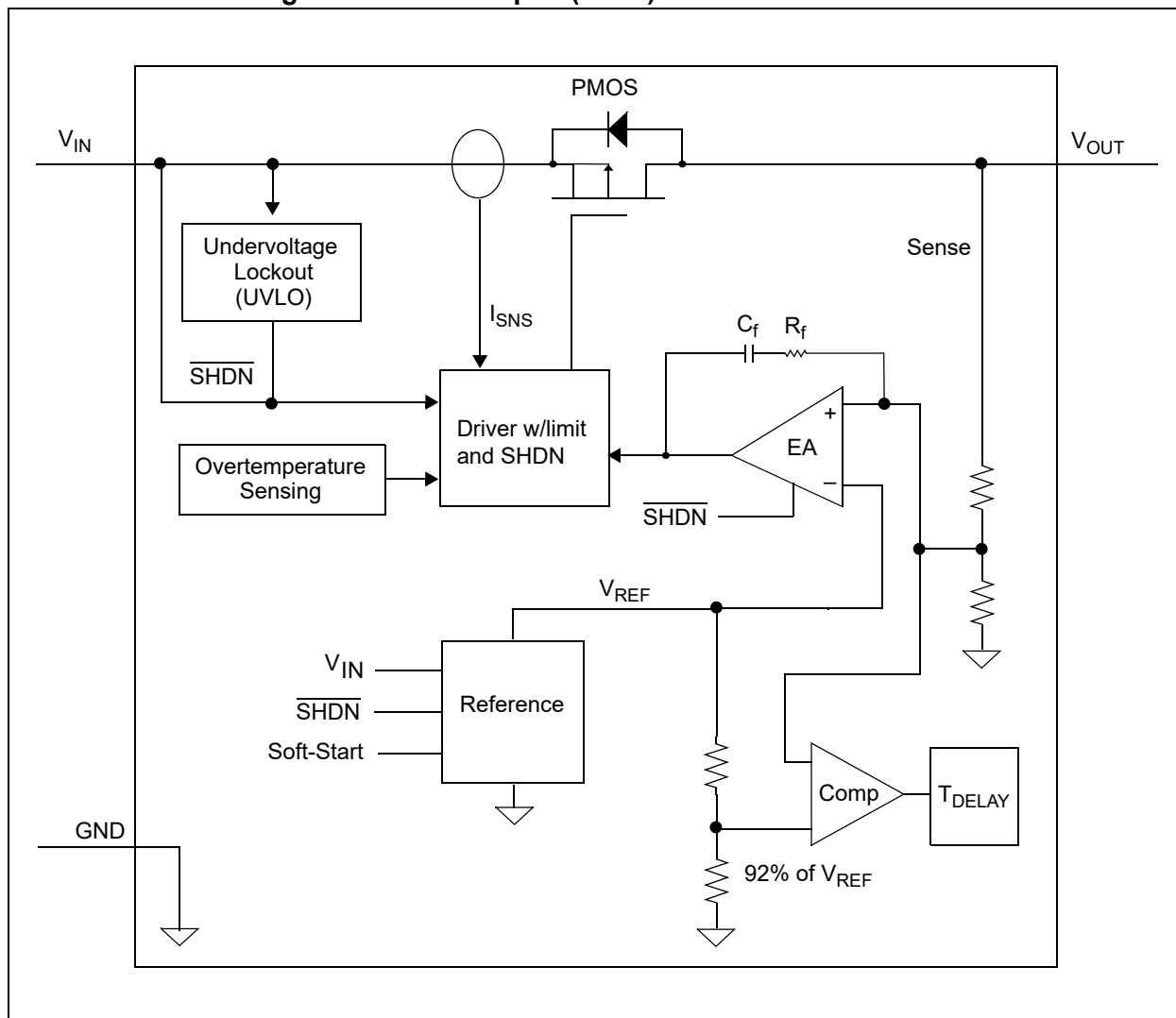


MCP1826/MCP1826S

Functional Block Diagram – Adjustable Output

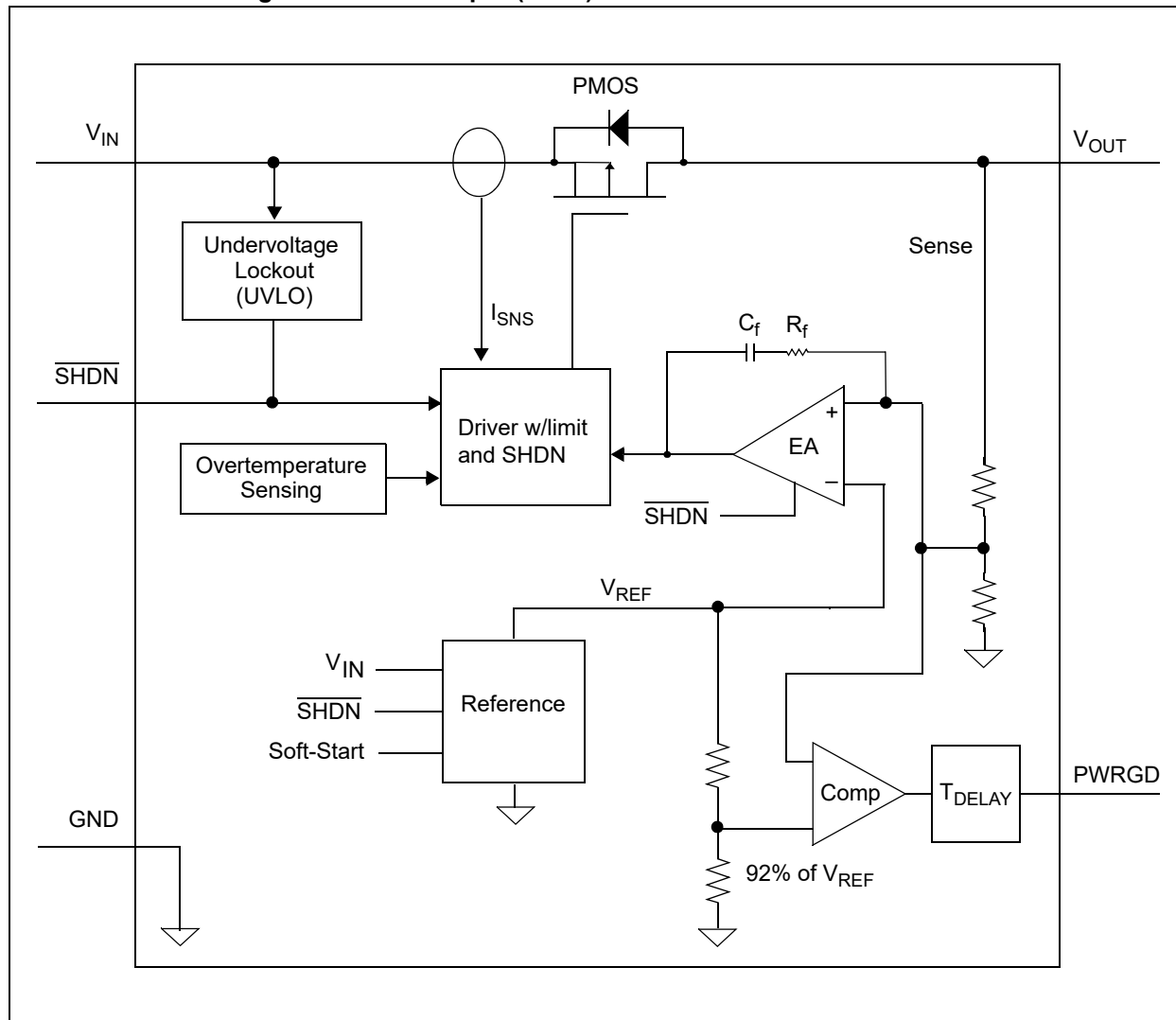


Functional Block Diagram – Fixed Output (3-Pin)



MCP1826/MCP1826S

Functional Block Diagram – Fixed Output (5-Pin)



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

| | |
|--|--------------------------------------|
| V_{IN} | 6.5V |
| Maximum Voltage on Any Pin .. (GND – 0.3V) to (V_{DD} + 0.3)V | |
| Maximum Power Dissipation..... | Internally-Limited (Note 6) |
| Output Short Circuit Duration..... | Continuous |
| Storage temperature | -65°C to +150°C |
| Maximum Junction Temperature, T_J | +150°C |
| ESD protection on all pins (HBM/MM) | ≥ 4 kV; ≥ 300V |

† **Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

AC/DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$, **Note 1**, $V_R = 1.8V$ for Adjustable Output, $I_{OUT} = 1\text{ mA}$, $C_{IN} = C_{OUT} = 4.7\text{ }\mu\text{F}$ (X7R Ceramic), $T_A = +25^\circ\text{C}$.
Boldface type applies for junction temperatures, T_J (**Note 7**) of **-40°C to +125°C**

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|--|---|---------------------------------|-----------------|---------------------------------|---------------|---|
| Input Operating Voltage | V_{IN} | 2.3 | | 6.0 | V | Note 1 |
| Input Quiescent Current | I_q | — | 120 | 220 | μA | $I_L = 0\text{ mA}$, $V_{OUT} = 0.8V$ to 5.0V |
| Input Quiescent Current for SHDN Mode | I_{SHDN} | — | 0.1 | 3 | μA | $\overline{\text{SHDN}} = \text{GND}$ |
| Maximum Output Current | I_{OUT} | 1000 | — | — | mA | $V_{IN} = 2.3V$ to 6.0V $V_R = 0.8V$ to 5.0V, Note 1 |
| Line Regulation | $\Delta V_{OUT} / (V_{OUT} \times \Delta V_{IN})$ | — | ±0.05 | ±0.20 | %/V | (Note 1) $\leq V_{IN} \leq 6V$ |
| Load Regulation | $\Delta V_{OUT} / V_{OUT}$ | -1.0 | ±0.5 | 1.0 | % | $I_{OUT} = 1\text{ mA}$ to 1000 mA, (Note 4) |
| Output Short Circuit Current | I_{OUT_SC} | — | 2.2 | — | A | $R_{LOAD} < 0.1\Omega$, Peak Current |
| Adjust Pin Characteristics (Adjustable Output Only) | | | | | | |
| Adjust Pin Reference Voltage | V_{ADJ} | 0.402 | 0.410 | 0.418 | V | $V_{IN} = 2.3V$ to $V_{IN} = 6.0V$, $I_{OUT} = 1\text{ mA}$ |
| Adjust Pin Leakage Current | I_{ADJ} | -10 | ±0.01 | +10 | nA | $V_{IN} = 6.0V$, $V_{ADJ} = 0V$ to 6V |
| Adjust Temperature Coefficient | TCV_{OUT} | — | 40 | — | ppm/°C | Note 3 |
| Fixed-Output Characteristics (Fixed Output Only) | | | | | | |
| Voltage Regulation | V_{OUT} | $V_R - 2.5\%$ | $V_R \pm 0.5\%$ | $V_R + 2.5\%$ | V | Note 2 |

- Note 1:** The minimum V_{IN} must meet two conditions: $V_{IN} \geq 2.3V$ and $V_{IN} \geq V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- 2:** V_R is the nominal regulator output voltage for the fixed cases. $V_R = 1.2V, 1.8V$, etc. V_R is the desired set point output voltage for the adjustable cases. $V_R = V_{ADJ} \cdot ((R_1/R_2)+1)$. **Figure 4-1**.
- 3:** $TCV_{OUT} = (V_{OUT-HIGH} - V_{OUT-LOW}) \cdot 10^6 / (V_R \cdot \Delta\text{Temperature})$. $V_{OUT-HIGH}$ is the highest voltage measured over the temperature range. $V_{OUT-LOW}$ is the lowest voltage measured over the temperature range.
- 4:** Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.
- 5:** Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its nominal value that was measured with an input voltage of $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- 6:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air. (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +150°C rating. Sustained junction temperatures above 150°C can impact device reliability.
- 7:** The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

MCP1826/MCP1826S

AC/DC CHARACTERISTICS (CONTINUED)

| Electrical Specifications: Unless otherwise noted, $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$, Note 1 , $V_R = 1.8V$ for Adjustable Output, $I_{OUT} = 1\text{ mA}$, $C_{IN} = C_{OUT} = 4.7\text{ }\mu\text{F}$ (X7R Ceramic), $T_A = +25^\circ\text{C}$. Boldface type applies for junction temperatures, T_J (Note 7) of -40°C to $+125^\circ\text{C}$ | | | | | | |
|--|-------------------------|------------------------|-------------|------------------------|--------------------------------|---|
| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
| Dropout Characteristics | | | | | | |
| Dropout Voltage | $V_{DROPOUT}$ | — | 250 | 400 | mV | Note 5 , $I_{OUT} = 1000\text{ mA}$, $V_{IN(MIN)} = 2.3V$ |
| Power Good Characteristics | | | | | | |
| PWRGD Input Voltage Operating Range | V_{PWRGD_VIN} | 1.0 1.2 | — — | 6.0 6.0 | V | $T_A = +25^\circ\text{C}$ $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$ For $V_{IN} < 2.3V$, $I_{SINK} = 100\text{ }\mu\text{A}$ |
| PWRGD Threshold Voltage (Referenced to V_{OUT}) | V_{PWRGD_TH} | 89 90 | 92 92 | 95 94 | % V_{OUT} | Falling Edge $V_{OUT} < 2.5V$ Fixed, $V_{OUT} = \text{Adj.}$ $V_{OUT} \geq 2.5V$ Fixed |
| PWRGD Threshold Hysteresis | V_{PWRGD_HYS} | 1.0 | 2.0 | 3.0 | % V_{OUT} | |
| PWRGD Output Voltage Low | V_{PWRGD_L} | — | 0.2 | 0.4 | V | $I_{PWRGD\ SINK} = 1.2\text{ mA}$, $ADJ = 0V$ |
| PWRGD Leakage | P_{PWRGD_LK} | — | 1 | — | nA | $V_{PWRGD} = V_{IN} = 6.0V$ |
| PWRGD Time Delay | T_{PG} | — | 125 | — | μs | Rising Edge $R_{PULLUP} = 10\text{ k}\Omega$ |
| Detect Threshold to PWRGD Active Time Delay | $T_{VDET-PWRGD}$ | — | 200 | — | μs | $V_{OUT} = V_{PWRGD_TH} + 20\text{ mV}$ to $V_{PWRGD_TH} - 20\text{ mV}$ |
| Shutdown Input | | | | | | |
| Logic High Input | $V_{SHDN-HIGH}$ | 45 | — | — | % V_{IN} | $V_{IN} = 2.3V$ to $6.0V$ |
| Logic Low Input | $V_{SHDN-LOW}$ | — | — | 15 | % V_{IN} | $V_{IN} = 2.3V$ to $6.0V$ |
| SHDN Input Leakage Current | \overline{SHDN}_{ILK} | -0.1 | ± 0.001 | +0.1 | μA | $V_{IN} = 6V$, $\overline{SHDN} = V_{IN}$, $SHDN = GND$ |
| AC Performance | | | | | | |
| Output Delay From \overline{SHDN} | T_{OR} | — | 100 | — | μs | $\overline{SHDN} = GND$ to V_{IN} $V_{OUT} = GND$ to $95\% V_R$ |
| Output Noise | e_N | — | 2.0 | — | $\mu\text{V}/\sqrt{\text{Hz}}$ | $I_{OUT} = 200\text{ mA}$, $f = 1\text{ kHz}$, $C_{OUT} = 10\text{ }\mu\text{F}$ (X7R Ceramic), $V_{OUT} = 2.5V$ |

- Note 1:** The minimum V_{IN} must meet two conditions: $V_{IN} \geq 2.3V$ and $V_{IN} \geq V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- Note 2:** V_R is the nominal regulator output voltage for the fixed cases. $V_R = 1.2V$, $1.8V$, etc. V_R is the desired set point output voltage for the adjustable cases. $V_R = V_{ADJ} \cdot ((R_1/R_2)+1)$. **Figure 4-1**.
- Note 3:** $TCV_{OUT} = (V_{OUT-HIGH} - V_{OUT-LOW}) \cdot 10^6 / (V_R \cdot \Delta\text{Temperature})$. $V_{OUT-HIGH}$ is the highest voltage measured over the temperature range. $V_{OUT-LOW}$ is the lowest voltage measured over the temperature range.
- Note 4:** Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.
- Note 5:** Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its nominal value that was measured with an input voltage of $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- Note 6:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air. (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum $+150^\circ\text{C}$ rating. Sustained junction temperatures above 150°C can impact device reliability.
- Note 7:** The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

AC/DC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$, **Note 1**, $V_R = 1.8V$ for Adjustable Output, $I_{OUT} = 1\text{ mA}$, $C_{IN} = C_{OUT} = 4.7\text{ }\mu\text{F}$ (X7R Ceramic), $T_A = +25^\circ\text{C}$.

Boldface type applies for junction temperatures, T_J (**Note 7**) of -40°C to $+125^\circ\text{C}$

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|-------------------------------------|-----------------|------|------|------|------------------|---|
| Power Supply Ripple Rejection Ratio | PSRR | — | 60 | — | dB | $f = 100\text{ Hz}$, $C_{OUT} = 4.7\text{ }\mu\text{F}$, $I_{OUT} = 100\text{ }\mu\text{A}$, $V_{INAC} = 100\text{ mV pk-pk}$, $C_{IN} = 0\text{ }\mu\text{F}$ |
| Thermal Shutdown Temperature | T_{SD} | — | 150 | — | $^\circ\text{C}$ | $I_{OUT} = 100\text{ }\mu\text{A}$, $V_{OUT} = 1.8V$, $V_{IN} = 2.8V$ |
| Thermal Shutdown Hysteresis | ΔT_{SD} | — | 10 | — | $^\circ\text{C}$ | $I_{OUT} = 100\text{ }\mu\text{A}$, $V_{OUT} = 1.8V$, $V_{IN} = 2.8V$ |

- Note 1:** The minimum V_{IN} must meet two conditions: $V_{IN} \geq 2.3V$ and $V_{IN} \geq V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- 2:** V_R is the nominal regulator output voltage for the fixed cases. $V_R = 1.2V$, $1.8V$, etc. V_R is the desired set point output voltage for the adjustable cases. $V_R = V_{ADJ} \cdot ((R_1/R_2)+1)$. **Figure 4-1**.
- 3:** $TCV_{OUT} = (V_{OUT-HIGH} - V_{OUT-LOW}) \cdot 10^6 / (V_R \cdot \Delta\text{Temperature})$. $V_{OUT-HIGH}$ is the highest voltage measured over the temperature range. $V_{OUT-LOW}$ is the lowest voltage measured over the temperature range.
- 4:** Load regulation is measured at a constant junction temperature using low duty-cycle pulse testing. Load regulation is tested over a load range from 1 mA to the maximum specified output current.
- 5:** Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below its nominal value that was measured with an input voltage of $V_{IN} = V_{OUT(MAX)} + V_{DROPOUT(MAX)}$.
- 6:** The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction to air. (i.e., T_A , T_J , θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum $+150^\circ\text{C}$ rating. Sustained junction temperatures above 150°C can impact device reliability.
- 7:** The junction temperature is approximated by soaking the device under test at an ambient temperature equal to the desired junction temperature. The test time is small enough such that the rise in the junction temperature over the ambient temperature is not significant.

TEMPERATURE SPECIFICATIONS

| Parameters | Sym. | Min. | Typ. | Max. | Units | Conditions |
|--------------------------------------|---------------|------|------|------|--------------------|--------------------------------------|
| Temperature Ranges | | | | | | |
| Operating Junction Temperature Range | T_J | -40 | — | +125 | $^\circ\text{C}$ | Steady State |
| Maximum Junction Temperature | T_J | — | — | +150 | $^\circ\text{C}$ | Transient |
| Storage Temperature Range | T_A | -65 | — | +150 | $^\circ\text{C}$ | |
| Thermal Package Resistances | | | | | | |
| Thermal Resistance, 3L-DDPAK | θ_{JA} | — | 31.4 | — | $^\circ\text{C/W}$ | 4-Layer JC51 Standard Board |
| | θ_{JC} | — | 3.0 | — | $^\circ\text{C/W}$ | |
| Thermal Resistance, 3L-TO-220 | θ_{JA} | — | 29.4 | — | $^\circ\text{C/W}$ | 4-Layer JC51 Standard Board |
| | θ_{JC} | — | 2.0 | — | $^\circ\text{C/W}$ | |
| Thermal Resistance, 3L-SOT-223 | θ_{JA} | — | 62 | — | $^\circ\text{C/W}$ | EIA/JEDEC JESD51-751-7 4 Layer Board |
| | θ_{JC} | — | 15.0 | — | $^\circ\text{C/W}$ | |
| Thermal Resistance, 5L-DDPAK | θ_{JA} | — | 31.2 | — | $^\circ\text{C/W}$ | 4-Layer JC51 Standard Board |
| | θ_{JC} | — | 3.0 | — | $^\circ\text{C/W}$ | |
| Thermal Resistance, 5L-TO-220 | θ_{JA} | — | 29.3 | — | $^\circ\text{C/W}$ | 4-Layer JC51 Standard Board |
| | θ_{JC} | — | 2.0 | — | $^\circ\text{C/W}$ | |
| Thermal Resistance, 5L-SOT-223 | θ_{JA} | — | 62 | — | $^\circ\text{C/W}$ | EIA/JEDEC JESD51-751-7 4 Layer Board |
| | θ_{JC} | — | 15.0 | — | $^\circ\text{C/W}$ | |

MCP1826/MCP1826S

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $C_{OUT} = 4.7 \mu F$ Ceramic (X7R), $C_{IN} = 4.7 \mu F$ Ceramic (X7R), $I_{OUT} = 1 \text{ mA}$, Temperature = $+25^\circ\text{C}$, $V_{IN} = V_{OUT} + 0.6\text{V}$, Fixed output.

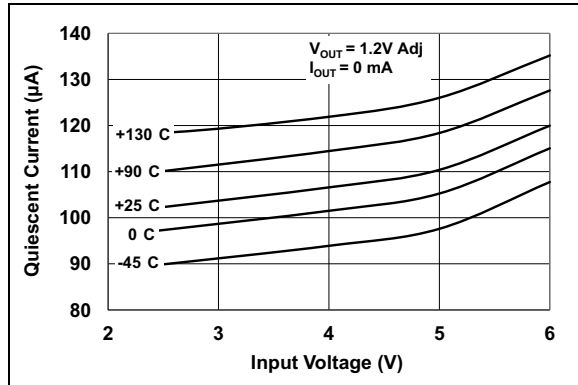


FIGURE 2-1: Quiescent Current vs. Input Voltage (Adjustable Version).

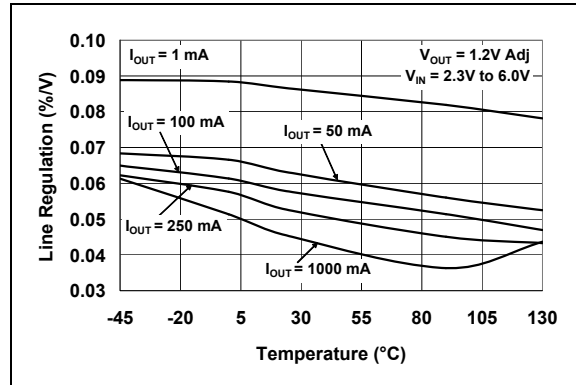


FIGURE 2-4: Line Regulation vs. Temperature (Adjustable Version).

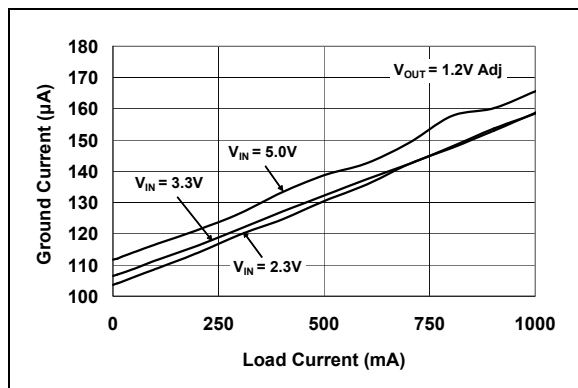


FIGURE 2-2: Ground Current vs. Load Current (Adjustable Version).

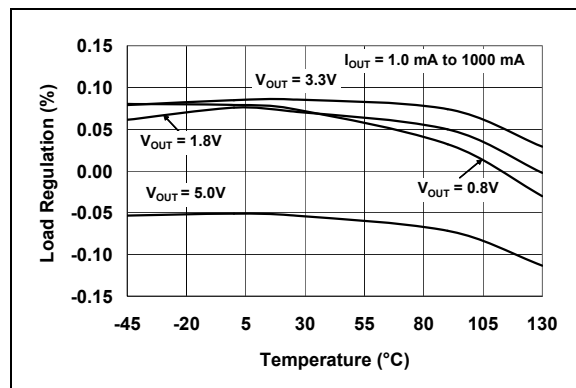


FIGURE 2-5: Load Regulation vs. Temperature (Adjustable Version).

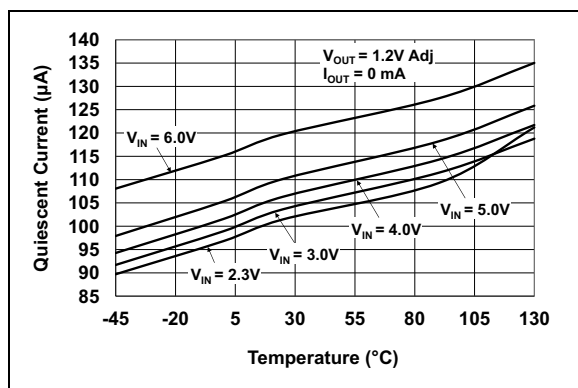


FIGURE 2-3: Quiescent Current vs. Junction Temperature (Adjustable Version).

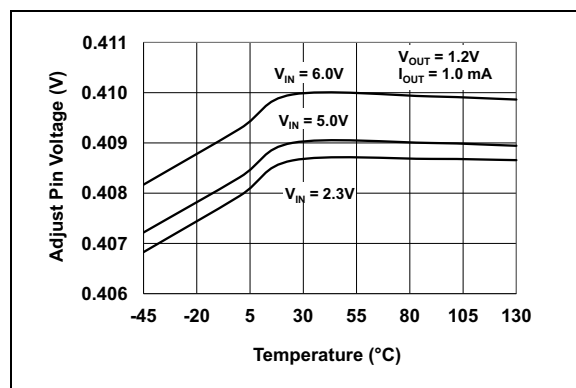


FIGURE 2-6: Adjust Pin Voltage vs. Temperature (Adjustable Version).

MCP1826/MCP1826S

Note: Unless otherwise indicated, $C_{OUT} = 4.7 \mu F$ Ceramic (X7R), $C_{IN} = 4.7 \mu F$ Ceramic (X7R), $I_{OUT} = 1 \text{ mA}$, Temperature = $+25^\circ\text{C}$, $V_{IN} = V_{OUT} + 0.6\text{V}$, Fixed output.

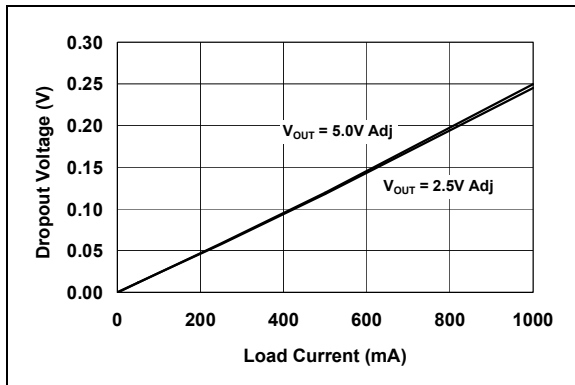


FIGURE 2-7: Dropout Voltage vs. Load Current (Adjustable Version).

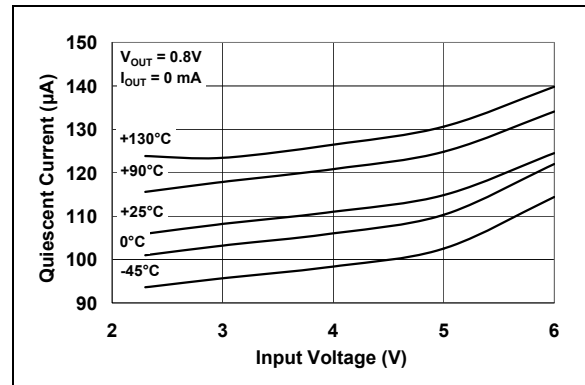


FIGURE 2-10: Quiescent Current vs. Input Voltage.

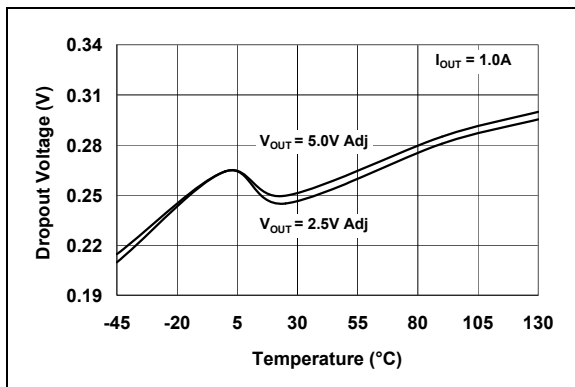


FIGURE 2-8: Dropout Voltage vs. Temperature (Adjustable Version).

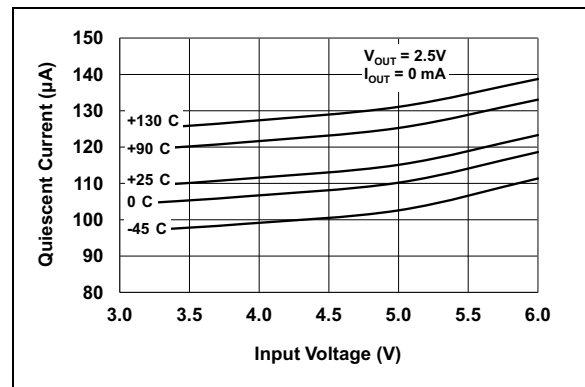


FIGURE 2-11: Quiescent Current vs. Input Voltage.

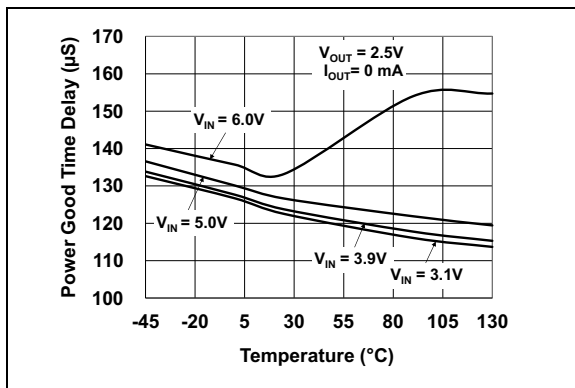


FIGURE 2-9: Power Good (PWRGD) Time Delay vs. Temperature.

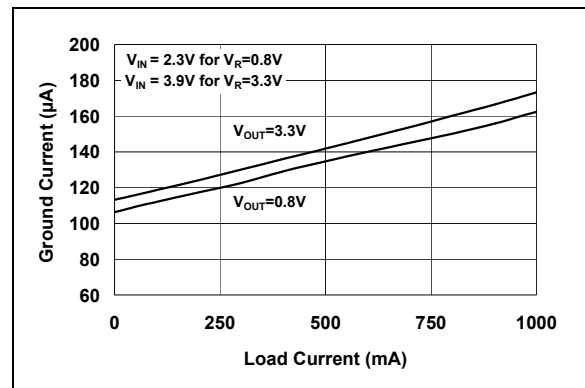


FIGURE 2-12: Ground Current vs. Load Current.

MCP1826/MCP1826S

Note: Unless otherwise indicated, $C_{OUT} = 4.7 \mu F$ Ceramic (X7R), $C_{IN} = 4.7 \mu F$ Ceramic (X7R), $I_{OUT} = 1 \text{ mA}$, Temperature = $+25^\circ\text{C}$, $V_{IN} = V_{OUT} + 0.6\text{V}$, Fixed output.

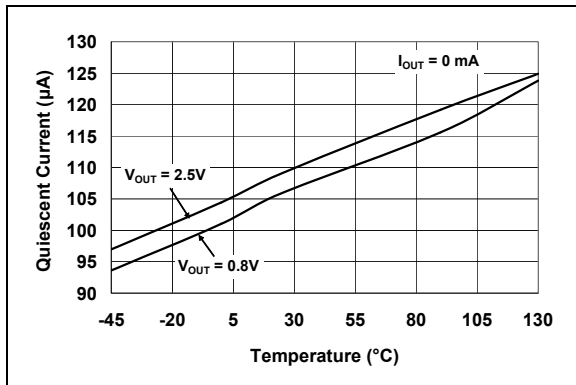


FIGURE 2-13: Quiescent Current vs. Temperature.

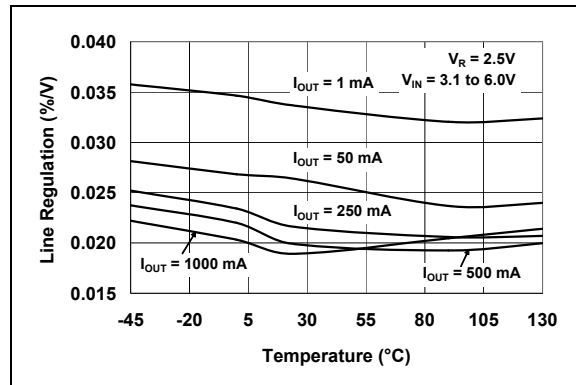


FIGURE 2-16: Line Regulation vs. Temperature.

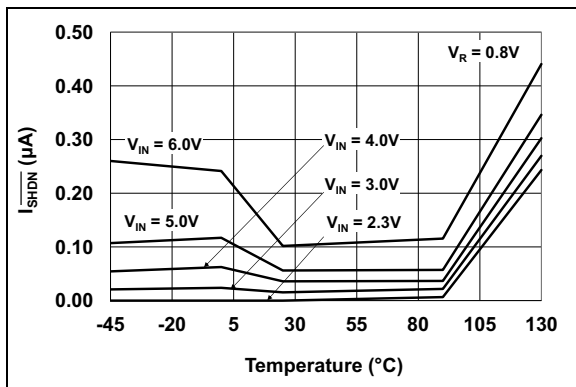


FIGURE 2-14: I_{SHDN} vs. Temperature.

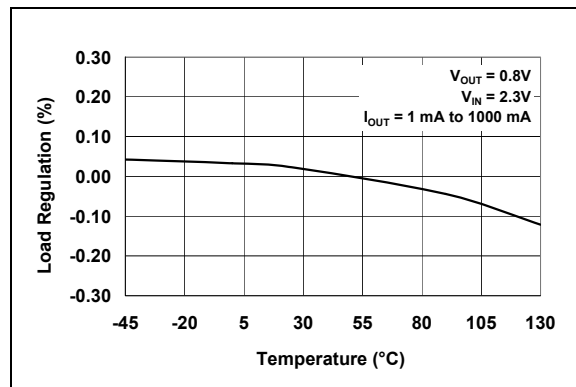


FIGURE 2-17: Load Regulation vs. Temperature ($V_{OUT} < 2.5\text{V}$ Fixed).

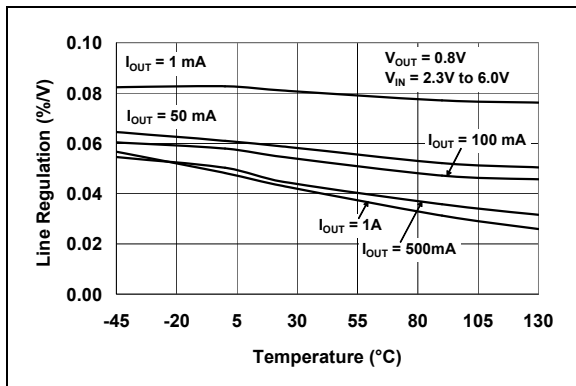


FIGURE 2-15: Line Regulation vs. Temperature.

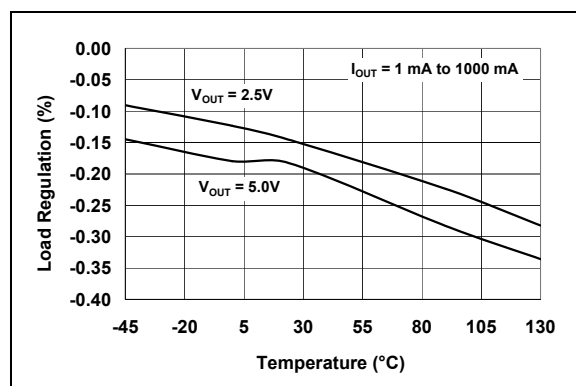


FIGURE 2-18: Load Regulation vs. Temperature ($V_{OUT} \geq 2.5\text{V}$ Fixed).

MCP1826/MCP1826S

Note: Unless otherwise indicated, $C_{OUT} = 4.7 \mu\text{F}$ Ceramic (X7R), $C_{IN} = 4.7 \mu\text{F}$ Ceramic (X7R), $I_{OUT} = 1 \text{ mA}$, Temperature = $+25^\circ\text{C}$, $V_{IN} = V_{OUT} + 0.6\text{V}$, Fixed output.

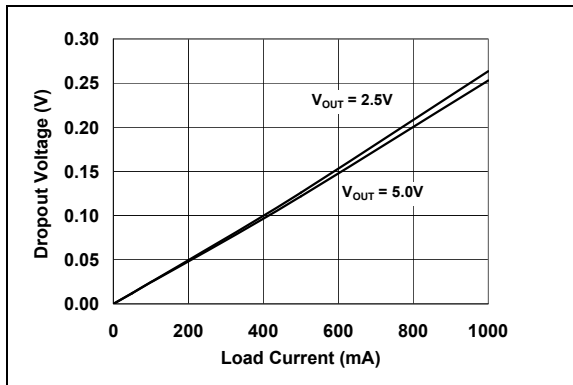


FIGURE 2-19: Dropout Voltage vs. Load Current.

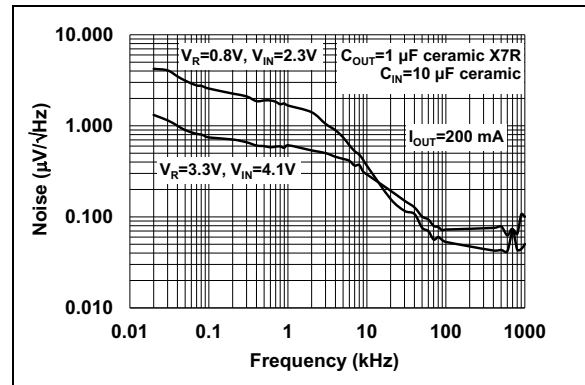


FIGURE 2-22: Output Noise Voltage Density vs. Frequency.

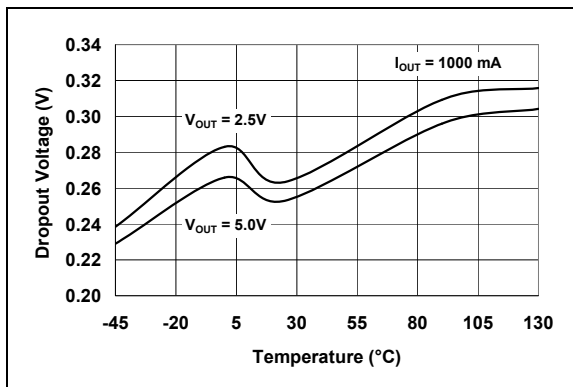


FIGURE 2-20: Dropout Voltage vs. Temperature.

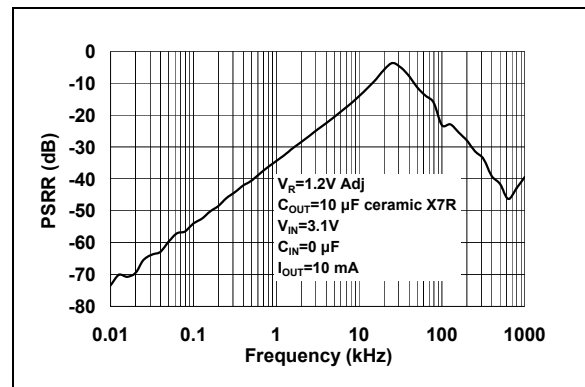


FIGURE 2-23: Power Supply Ripple Rejection (PSRR) vs. Frequency (Adjustable).

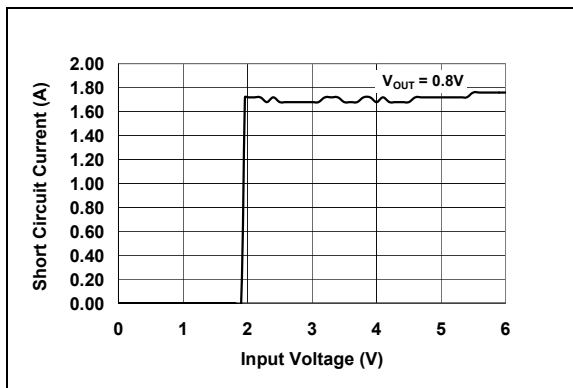


FIGURE 2-21: Short Circuit Current vs. Input Voltage.

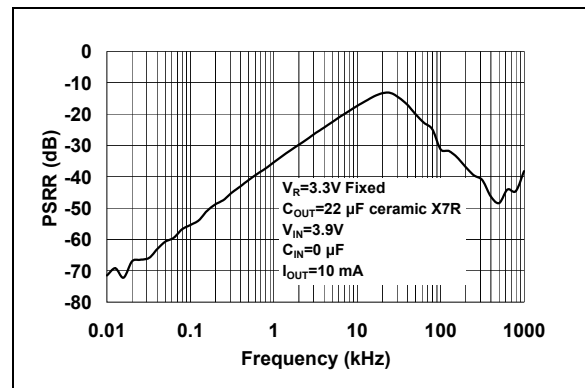


FIGURE 2-24: Power Supply Ripple Rejection (PSRR) vs. Frequency.

MCP1826/MCP1826S

Note: Unless otherwise indicated, $C_{OUT} = 4.7 \mu F$ Ceramic (X7R), $C_{IN} = 4.7 \mu F$ Ceramic (X7R), $I_{OUT} = 1 \text{ mA}$, Temperature = +25°C, $V_{IN} = V_{OUT} + 0.6 \text{ V}$, Fixed output.

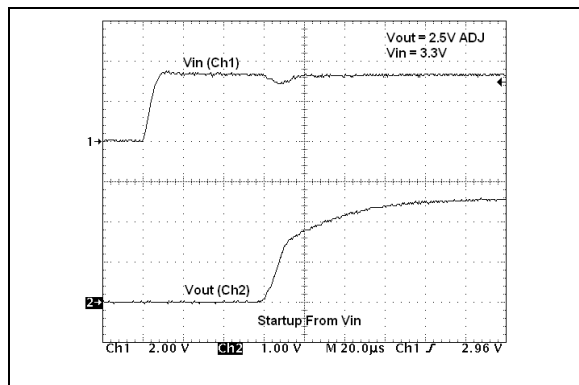


FIGURE 2-25: 2.5V (Adj.) Start-up from V_{IN} .

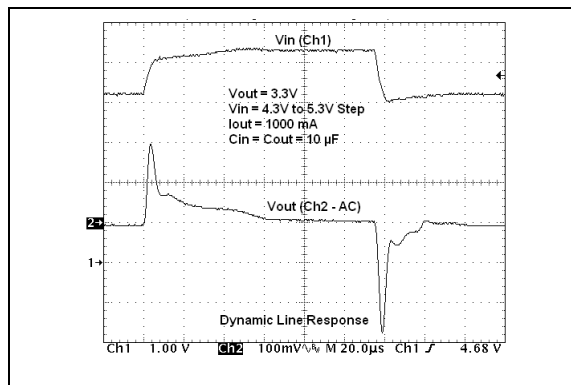


FIGURE 2-28: Dynamic Line Response.

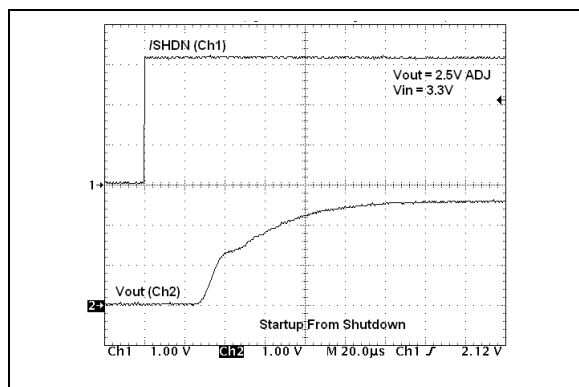


FIGURE 2-26: 2.5V (Adj.) Start-up from Shutdown.

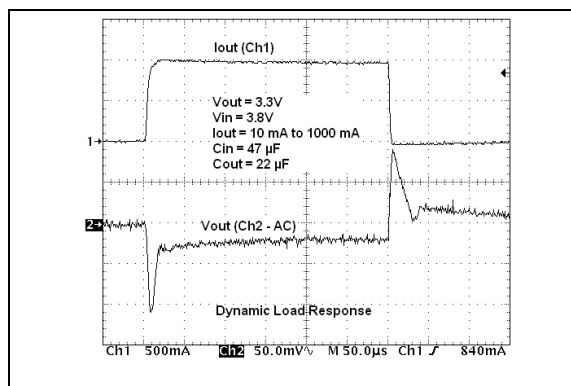


FIGURE 2-29: Dynamic Load Response (10 mA to 1000 mA).

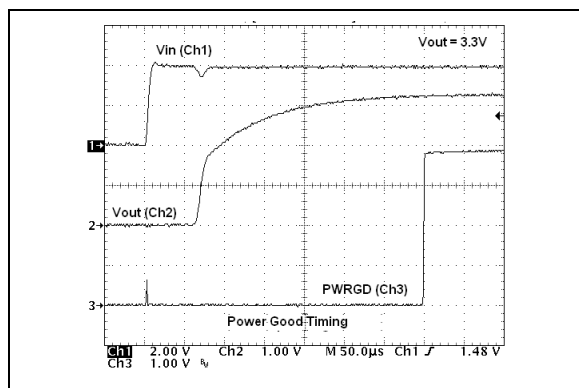


FIGURE 2-27: Power Good (PWRGD) Timing.

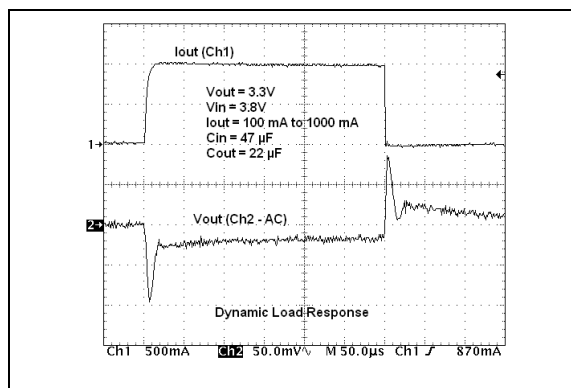


FIGURE 2-30: Dynamic Load Response (100 mA to 1000 mA).

3.0 PIN DESCRIPTION

The descriptions of the pins are listed in [Table 3-1](#).

TABLE 3-1: PIN FUNCTION TABLE

| 3-Pin Fixed Output | 5-Pin Fixed Output | Adjustable Output | Name | Description |
|--------------------|--------------------|-------------------|--------------------------|---|
| — | 1 | 1 | $\overline{\text{SHDN}}$ | Shutdown Control Input (active-low) |
| 1 | 2 | 2 | V_{IN} | Input Voltage Supply |
| 2 | 3 | 3 | GND | Ground |
| 3 | 4 | 4 | V_{OUT} | Regulated Output Voltage |
| — | 5 | — | PWRGD | Power Good Output |
| — | — | 5 | ADJ | Voltage Adjust/Sense Input |
| Exposed Pad | Exposed Pad | Exposed Pad | EP | Exposed Pad of the Package (ground potential) |

3.1 Shutdown Control Input ($\overline{\text{SHDN}}$)

The $\overline{\text{SHDN}}$ input is used to turn the LDO output voltage on and off. When the $\overline{\text{SHDN}}$ input is at a logic-high level, the LDO output voltage is enabled. When the $\overline{\text{SHDN}}$ input is pulled to a logic-low level, the LDO output voltage is disabled. When the $\overline{\text{SHDN}}$ input is pulled low, the PWRGD output also goes low and the LDO enters a low quiescent current shutdown state where the typical quiescent current is 0.1 μA .

3.2 Input Voltage Supply (V_{IN})

Connect the unregulated or regulated input voltage source to V_{IN} . If the input voltage source is located several inches away from the LDO, or the input source is a battery, it is recommended that an input capacitor be used. A typical input capacitance value of 1 μF to 10 μF should be sufficient for most applications.

3.3 Ground (GND)

Connect the GND pin of the LDO to a quiet circuit ground. This will help the LDO power supply rejection ratio and noise performance. The ground pin of the LDO only conducts the quiescent current of the LDO (typically 120 μA), so a heavy trace is not required. For applications have switching or noisy inputs tie the GND pin to the return of the output capacitor. Ground planes help lower inductance and voltage spikes caused by fast transient load currents and are recommended for applications that are subjected to fast load transients.

3.4 Regulated Output Voltage (V_{OUT})

The V_{OUT} pin is the regulated output voltage of the LDO. A minimum output capacitance of 1.0 μF is required for LDO stability. The MCP1826/MCP1826S is stable with ceramic, tantalum and aluminum-electrolytic capacitors. See [Section 4.3 “Output Capacitor”](#) for output capacitor selection guidance.

3.5 Power Good Output (PWRGD)

The PWRGD output is an open-drain output used to indicate when the LDO output voltage is within 92% (typically) of its nominal regulation value. The PWRGD threshold has a typical hysteresis value of 2%. The PWRGD output is delayed by 200 μs (typical) from the time the LDO output is within 92% + 3% (max hysteresis) of the regulated output value on power-up. This delay time is internally fixed.

3.6 Output Voltage Adjust Input (ADJ)

For adjustable applications, the output voltage is connected to the ADJ input through a resistor divider that sets the output voltage regulation value. This provides the user the capability to set the output voltage to any value they desire within the 0.8V to 5.0V range of the device.

3.7 Exposed Pad (EP)

The DPAK and TO-220 package have an exposed tab on the package. A heat sink may be mounted to the tab to aid in the removal of heat from the package during operation. The exposed tab is at the ground potential of the LDO.

MCP1826/MCP1826S

4.0 DEVICE OVERVIEW

The MCP1826/MCP1826S is a high output current, Low Dropout (LDO) voltage regulator. The low dropout voltage of 300 mV typical at 1000 mA of current makes it ideal for battery-powered applications. Unlike other high output current LDOs, the MCP1826/MCP1826S only draws a maximum of 220 μ A of quiescent current. The MCP1826 has a shutdown control input and a power good output.

4.1 LDO Output Voltage

The 5-pin MCP1826 LDO is available with either a fixed output voltage or an adjustable output voltage. The output voltage range is 0.8V to 5.0V for both versions. The 3-pin MCP1826S LDO is available as a fixed voltage device.

4.1.1 ADJUST INPUT

The adjustable version of the MCP1826 uses the ADJ pin (pin 5) to get the output voltage feedback for output voltage regulation. This allows the user to set the output voltage of the device with two external resistors. The nominal voltage for ADJ is 0.41V.

Figure 4-1 shows the adjustable version of the MCP1826. Resistors R_1 and R_2 form the resistor divider network necessary to set the output voltage. With this configuration, the equation for setting V_{OUT} is:

EQUATION 4-1:

$$V_{OUT} = V_{ADJ} \left(\frac{R_1 + R_2}{R_2} \right)$$

Where:

V_{OUT} = LDO Output Voltage

V_{ADJ} = ADJ Pin Voltage (typically 0.41V)

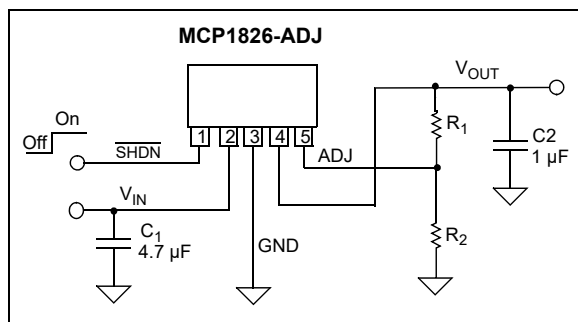


FIGURE 4-1: Typical adjustable output voltage application circuit.

The allowable resistance value range for resistor R_2 is from 10 k Ω to 200 k Ω . Solving the equation for R_1 yields the following equation:

EQUATION 4-2:

$$R_1 = R_2 \left(\frac{V_{OUT} - V_{ADJ}}{V_{ADJ}} \right)$$

Where:

V_{OUT} = LDO Output Voltage

V_{ADJ} = ADJ Pin Voltage (typically 0.41V)

4.2 Output Current and Current Limiting

The MCP1826/MCP1826S LDO is tested and ensured to supply a minimum of 1000 mA of output current. The MCP1826/MCP1826S has no minimum output load, so the output load current can go to 0 mA and the LDO will continue to regulate the output voltage to within tolerance.

The MCP1826/MCP1826S also incorporates an output current limit. If the output voltage falls below 0.7V due to an overload condition (usually represents a shorted load condition), the output current is limited to 2.2A (typical). If the overload condition is a soft overload, the MCP1826/MCP1826S will supply higher load currents of up to 2.5A. The MCP1826/MCP1826S should not be operated in this condition continuously as it may result in failure of the device. However, this does allow for device usage in applications that have higher pulsed load currents having an average output current value of 1000 mA or less.

Output overload conditions may also result in an over-temperature shutdown of the device. If the junction temperature rises above 150°C, the LDO will shut down the output voltage. See [Section 4.8 “Overtemperature Protection”](#) for more information on overtemperature shutdown.

4.3 Output Capacitor

The MCP1826/MCP1826S requires a minimum output capacitance of 1 μ F for output voltage stability. Ceramic capacitors are recommended because of their size, cost and environmental robustness qualities.

Aluminum-electrolytic and tantalum capacitors can be used on the LDO output as well. The Equivalent Series Resistance (ESR) of the electrolytic output capacitor must be no greater than 1 ohm. The output capacitor should be located as close to the LDO output as is practical. Ceramic materials X7R and X5R have low temperature coefficients and are well within the acceptable ESR range required. A typical 1 μ F X7R 0805 capacitor has an ESR of 50 milli-ohms.

Larger LDO output capacitors can be used with the MCP1826/MCP1826S to improve dynamic performance and power supply ripple rejection performance. A maximum of 22 μF is recommended. Aluminum-electrolytic capacitors are not recommended for low-temperature applications of $\leq -25^{\circ}\text{C}$.

4.4 Input Capacitor

Low input source impedance is necessary for the LDO output to operate properly. When operating from batteries, or in applications with long lead length (> 10 inches) between the input source and the LDO, some input capacitance is recommended. A minimum of 1.0 μF to 4.7 μF is recommended for most applications.

For applications that have output step load requirements, the input capacitance of the LDO is very important. The input capacitance provides the LDO with a good local low-impedance source to pull the transient currents from in order to respond quickly to the output load step. For good step response performance, the input capacitor should be of equivalent (or higher) value than the output capacitor. The capacitor should be placed as close to the input of the LDO, as is practical. Larger input capacitors will also help reduce any high-frequency noise on the input and output of the LDO and reduce the effects of any inductance that exists between the input source voltage and the input capacitance of the LDO.

4.5 Power Good Output (PWRGD)

The PWRGD output is used to indicate when the output voltage of the LDO is within 92% (typical value, see [Section 1.0 “Electrical Characteristics”](#) for Minimum and Maximum specifications) of its nominal regulation value.

As the output voltage of the LDO rises, the PWRGD output will be held low until the output voltage has exceeded the power good threshold plus the hysteresis value. Once this threshold has been exceeded, the power good time delay is started (shown as T_{PG} in the Electrical Characteristics table). The power good time delay is fixed at 125 μs (typical). After the time delay period, the PWRGD output will go high, indicating that the output voltage is stable and within regulation limits.

If the output voltage of the LDO falls below the power good threshold, the power good output will transition low. The power good circuitry has a 200 μs delay when detecting a falling output voltage, which helps to increase noise immunity of the power good output and avoid false triggering of the power good output during fast output transients. See [Figure 4-2](#) for power good timing characteristics.

When the LDO is put into Shutdown mode using the $\overline{\text{SHDN}}$ input, the power good output is pulled low immediately, indicating that the output voltage will be out of regulation. The timing diagram for the power good output when using the shutdown input is shown in [Figure 4-3](#).

The power good output is an open-drain output that can be pulled up to any voltage that is equal to or less than the LDO input voltage. This output is capable of sinking 1.2 mA ($V_{PWRGD} < 0.4\text{V}$ maximum).

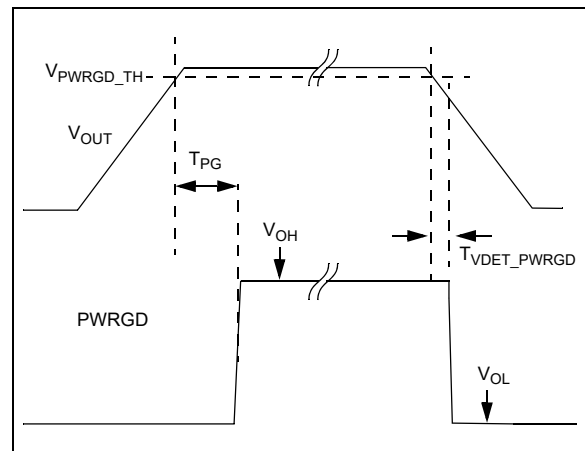


FIGURE 4-2: Power Good Timing.

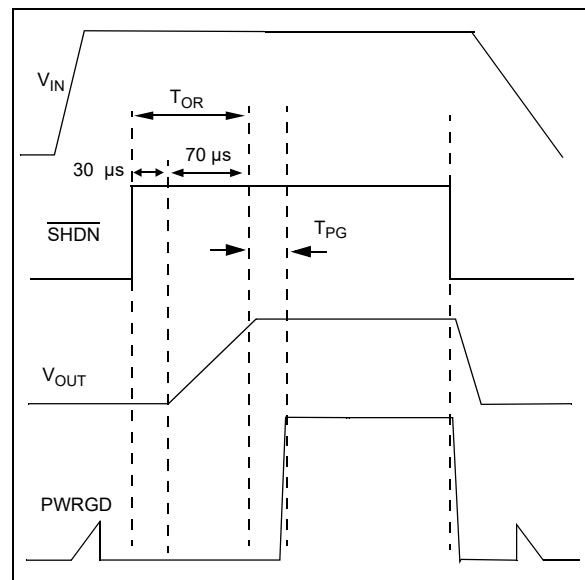


FIGURE 4-3: Power Good Timing from Shutdown.

MCP1826/MCP1826S

4.6 Shutdown Input ($\overline{\text{SHDN}}$)

The $\overline{\text{SHDN}}$ input is an active-low input signal that turns the LDO on and off. The $\overline{\text{SHDN}}$ threshold is a percentage of the input voltage. The typical value of this shutdown threshold is 30% of V_{IN} , with minimum and maximum limits over the entire operating temperature range of 45% and 15%, respectively.

The $\overline{\text{SHDN}}$ input will ignore low-going pulses (pulses meant to shut down the LDO) that are up to 400 ns in pulse width. If the shutdown input is pulled low for more than 400 ns, the LDO will enter Shutdown mode. This small bit of filtering helps to reject any system noise spikes on the shutdown input signal.

On the rising edge of the $\overline{\text{SHDN}}$ input, the shutdown circuitry has a 30 μs delay before allowing the LDO output to turn on. This delay helps to reject any false turn-on signals or noise on the $\overline{\text{SHDN}}$ input signal. After the 30 μs delay, the LDO output enters its soft-start period as it rises from 0V to its final regulation value. If the $\overline{\text{SHDN}}$ input signal is pulled low during the 30 μs delay period, the timer will be reset and the delay time will start over again on the next rising edge of the $\overline{\text{SHDN}}$ input. The total time from the $\overline{\text{SHDN}}$ input going high (turn-on) to the LDO output being in regulation is typically 100 μs . See Figure 4-4 for a timing diagram of the $\overline{\text{SHDN}}$ input.

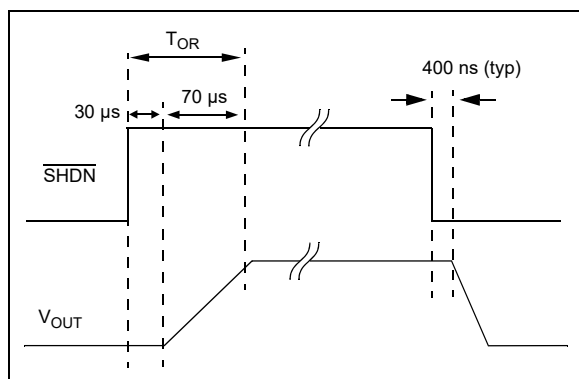


FIGURE 4-4: Shutdown Input Timing Diagram.

4.7 Dropout Voltage and Undervoltage Lockout

Dropout voltage is defined as the input-to-output voltage differential at which the output voltage drops 2% below the nominal value that was measured with a $V_{\text{R}} + 0.5\text{V}$ differential applied. The MCP1826/MCP1826S LDO has a very low dropout voltage specification of 250 mV (typical) at 1000 mA of output current. See Section 1.0 “Electrical Characteristics” for maximum dropout voltage specifications.

The MCP1826/MCP1826S LDO operates across an input voltage range of 2.3V to 6.0V and incorporates input Undervoltage Lockout (UVLO) circuitry that keeps the LDO output voltage off until the input voltage reaches a minimum of 2.00V (typical) on the rising edge of the input voltage. As the input voltage falls, the LDO output will remain on until the input voltage level reaches 1.82V (typical).

Since the MCP1826/MCP1826S LDO undervoltage lockout activates at 1.82V as the input voltage is falling, the dropout voltage specification does not apply for output voltages that are less than 1.8V.

For high-current applications, voltage drops across the PCB traces must be taken into account. The trace resistances can cause significant voltage drops between the input voltage source and the LDO. For applications with input voltages near 2.3V, these PCB trace voltage drops can sometimes lower the input voltage enough to trigger a shutdown due to undervoltage lockout.

4.8 Overtemperature Protection

The MCP1826/MCP1826S LDO has temperature-sensing circuitry to prevent the junction temperature from exceeding approximately 150°C. If the LDO junction temperature does reach 150°C, the LDO output will be turned off until the junction temperature cools to approximately 140°C, at which point the LDO output will automatically resume normal operation. If the internal power dissipation continues to be excessive, the device will again shut off. The junction temperature of the die is a function of power dissipation, ambient temperature and package thermal resistance. See Section 5.0 “Application Circuits/Issues” for more information on LDO power dissipation and junction temperature.

5.0 APPLICATION CIRCUITS/ISSUES

5.1 Typical Application

The MCP1826/MCP1826S is used for applications that require high LDO output current and a power good output.

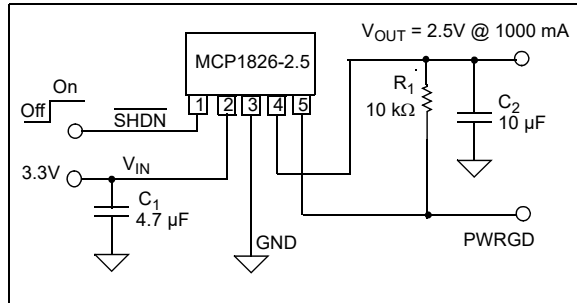


FIGURE 5-1: Typical Application Circuit.

5.1.1 APPLICATION CONDITIONS

- Package Type = TO-220-5
- Input Voltage Range = $3.3V \pm 5\%$
- V_{IN} maximum = 3.465V
- V_{IN} minimum = 3.135V
- $V_{DROPOUT(max)}$ = 0.400V
- V_{OUT} (typical) = 2.5V
- I_{OUT} = 1000 mA maximum
- P_{DISS} (typical) = 0.965W
- Temperature Rise = 28.27°C

5.2 Power Calculations

5.2.1 POWER DISSIPATION

The internal power dissipation within the MCP1826/MCP1826S is a function of input voltage, output voltage, output current and quiescent current. Equation 5-1 can be used to calculate the internal power dissipation for the LDO.

EQUATION 5-1:

$$P_{LDO} = (V_{IN(MAX)} - V_{OUT(MIN)}) \times I_{OUT(MAX)}$$

Where:

- P_{LDO} = LDO Pass device internal power dissipation
- $V_{IN(MAX)}$ = Maximum input voltage
- $V_{OUT(MIN)}$ = LDO minimum output voltage

In addition to the LDO pass element power dissipation, there is power dissipation within the MCP1826/MCP1826S as a result of quiescent or ground current. The power dissipation as a result of the ground current can be calculated using the following equation:

EQUATION 5-2:

$$P_{I(GND)} = V_{IN(MAX)} \times I_{VIN}$$

Where:

- $P_{I(GND)}$ = Power dissipation due to the quiescent current of the LDO
- $V_{IN(MAX)}$ = Maximum input voltage
- I_{VIN} = Current flowing in the V_{IN} pin with no LDO output current (LDO quiescent current)

The total power dissipated within the MCP1826/MCP1826S is the sum of the power dissipated in the LDO pass device and the $P_{I(GND)}$ term. Because of the CMOS construction, the typical I_{GND} for the MCP1826/MCP1826S is 120 μA. Operating at a maximum V_{IN} of 3.465V results in a power dissipation of 0.12 milli-Watts for a 2.5V output. For most applications, this is small compared to the LDO pass device power dissipation and can be neglected.

The maximum continuous operating junction temperature specified for the MCP1826/MCP1826S is +125°C. To estimate the internal junction temperature of the MCP1826/MCP1826S, the total internal power dissipation is multiplied by the thermal resistance from junction-to-ambient ($R_{\theta JA}$) of the device. The thermal resistance from junction to ambient for the TO-220-5 package is estimated at 29.3°C/W.

EQUATION 5-3:

$$T_{J(MAX)} = P_{TOTAL} \times R_{\theta JA} + T_{A(MAX)}$$

- $T_{J(MAX)}$ = Maximum continuous junction temperature
- P_{TOTAL} = Total device power dissipation
- $R_{\theta JA}$ = Thermal resistance from junction to ambient
- $T_{A(MAX)}$ = Maximum ambient temperature

MCP1826/MCP1826S

The maximum power dissipation capability for a package can be calculated given the junction-to-ambient thermal resistance and the maximum ambient temperature for the application. Equation 5-4 can be used to determine the package maximum internal power dissipation.

EQUATION 5-4:

$$P_{D(MAX)} = \frac{(T_{J(MAX)} - T_{A(MAX)})}{R\theta_{JA}}$$

$P_{D(MAX)}$ = Maximum device power dissipation

$T_{J(MAX)}$ = Maximum continuous junction temperature

$T_{A(MAX)}$ = Maximum ambient temperature

$R\theta_{JA}$ = Thermal resistance from junction to ambient

EQUATION 5-5:

$$T_{J(RISE)} = P_{D(MAX)} \times R\theta_{JA}$$

$T_{J(RISE)}$ = Rise in device junction temperature over the ambient temperature

$P_{D(MAX)}$ = Maximum device power dissipation

$R\theta_{JA}$ = Thermal resistance from junction to ambient

EQUATION 5-6:

$$T_J = T_{J(RISE)} + T_A$$

T_J = Junction temperature

$T_{J(RISE)}$ = Rise in device junction temperature over the ambient temperature

T_A = Ambient temperature

5.3 Typical Application

Internal power dissipation, junction temperature rise, junction temperature and maximum power dissipation is calculated in the following example. The power dissipation as a result of ground current is small enough to be neglected.

5.3.1 POWER DISSIPATION EXAMPLE

Package

Package Type = TO-220-5

Input Voltage

$V_{IN} = 3.3V \pm 5\%$

LDO Output Voltage and Current

$V_{OUT} = 2.5V$

$I_{OUT} = 1000 \text{ mA}$

Maximum Ambient Temperature

$T_{A(MAX)} = 60^\circ\text{C}$

Internal Power Dissipation

$P_{LDO(MAX)} = (V_{IN(MAX)} - V_{OUT(MIN)}) \times I_{OUT(MAX)}$

$P_{LDO} = ((3.3V \times 1.05) - (2.5V \times 0.975))$
 $\times 1000 \text{ mA}$

$P_{LDO} = 1.028 \text{ Watts}$

5.3.1.1 Device Junction Temperature Rise

The internal junction temperature rise is a function of internal power dissipation and the thermal resistance from junction to ambient for the application. The thermal resistance from junction-to-ambient ($R\theta_{JA}$) is derived from EIA/JEDEC standards for measuring thermal resistance. The EIA/JEDEC specification is JESD51. The standard describes the test method and board specifications for measuring the thermal resistance from junction to ambient. The actual thermal resistance for a particular application can vary depending on many factors such as copper area and thickness. Refer to AN792, "A Method to Determine How Much Power a SOT23 Can Dissipate in an Application" (DS00792), for more information regarding this subject.

$T_{J(RISE)} = P_{TOTAL} \times R\theta_{JA}$

$T_{J(RISE)} = 1.028 \text{ W} \times 29.3^\circ\text{C/W}$

$T_{J(RISE)} = 30.12^\circ\text{C}$

5.3.1.2 Junction Temperature Estimate

To estimate the internal junction temperature, the calculated temperature rise is added to the ambient or offset temperature. For this example, the worst-case junction temperature is estimated below:

$$T_J = T_{J(RISE)} + T_{A(MAX)}$$

$$T_J = 30.12^{\circ}\text{C} + 60.0^{\circ}\text{C}$$

$$T_J = 90.12^{\circ}\text{C}$$

5.3.1.3 Maximum Package Power Dissipation at 60°C Ambient Temperature

TO-220-5 (29.3° C/W R_{θJA}):

$$P_{D(MAX)} = (125^{\circ}\text{C} - 60^{\circ}\text{C}) / 29.3^{\circ}\text{C/W}$$

$$P_{D(MAX)} = 2.218\text{W}$$

DDPAK-5 (31.2°C/Watt R_{θJA}):

$$P_{D(MAX)} = (125^{\circ}\text{C} - 60^{\circ}\text{C}) / 31.2^{\circ}\text{C/W}$$

$$P_{D(MAX)} = 2.083\text{W}$$

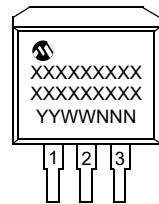
From this table, you can see the difference in maximum allowable power dissipation between the TO-220-5 package and the DDPK-5 package.

MCP1826/MCP1826S

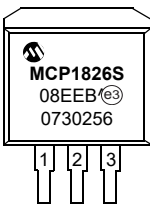
6.0 PACKAGING INFORMATION

6.1 Package Marking Information

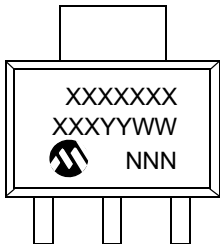
3-Lead DDPAK (MCP1826S)



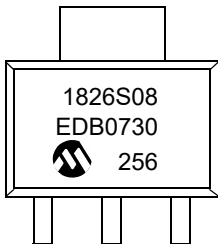
Example:



3-Lead SOT-223 (MCP1826S)



Example:



3-Lead TO-220 (MCP1826S)



Example:



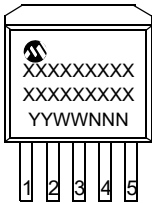
| | | |
|----------------|--------|--|
| Legend: | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * | This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. |

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

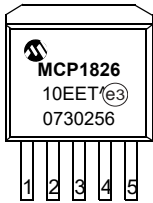
MCP1826/MCP1826S

Package Marking Information (Continued)

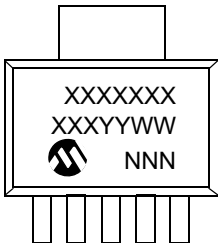
5-Lead DDPAK (MCP1826)



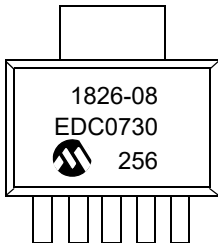
Example:



5-Lead SOT-223 (MCP1826)



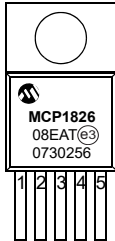
Example:



5-Lead TO-220 (MCP1826)



Example:



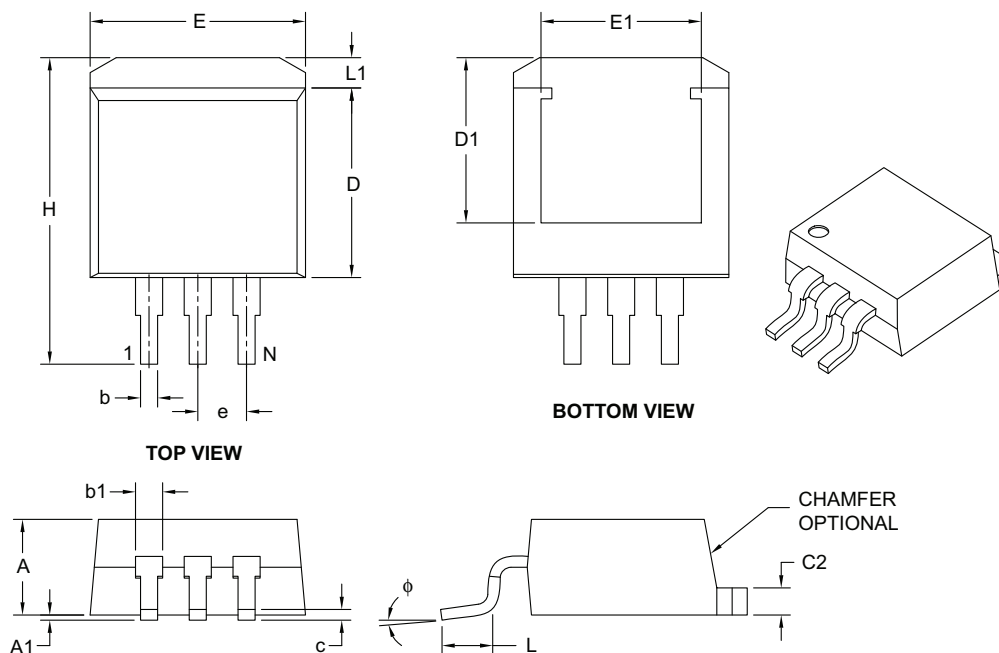
| | | |
|----------------|--------|--|
| Legend: | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * | This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. |

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

MCP1826/MCP1826S

3-Lead Plastic (EB) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | INCHES | | |
|-----------------------|----|-------|----------|-----|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Pins | N | | 3 | | |
| Pitch | e | | .100 BSC | | |
| Overall Height | A | | .160 | — | .190 |
| Standoff § | A1 | | .000 | — | .010 |
| Overall Width | E | | .380 | — | .420 |
| Exposed Pad Width | E1 | | .245 | — | — |
| Molded Package Length | D | | .330 | — | .380 |
| Overall Length | H | | .549 | — | .625 |
| Exposed Pad Length | D1 | | .270 | — | — |
| Lead Thickness | c | | .014 | — | .029 |
| Pad Thickness | C2 | | .045 | — | .065 |
| Lower Lead Width | b | | .020 | — | .039 |
| Upper Lead Width | b1 | | .045 | — | .070 |
| Foot Length | L | | .068 | — | .110 |
| Pad Length | L1 | | — | — | .067 |
| Foot Angle | φ | | 0° | — | 8° |

Notes:

- § Significant Characteristic.
- Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

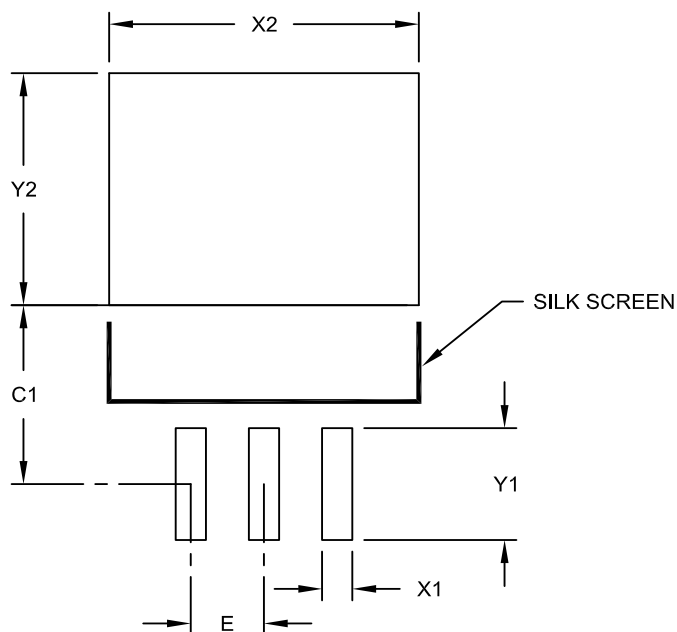
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-011B

MCP1826/MCP1826S

3-Lead Plastic (EB) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | INCHES | | |
|-------------------------|-------|----------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | .100 BSC | | |
| Pad Width | X2 | | | .423 |
| Pad Length | Y2 | | | .327 |
| Contact Pad Spacing | C1 | | .252 | |
| Contact Pad Width (X3) | X1 | | | .041 |
| Contact Pad Length (X3) | Y1 | | | .157 |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

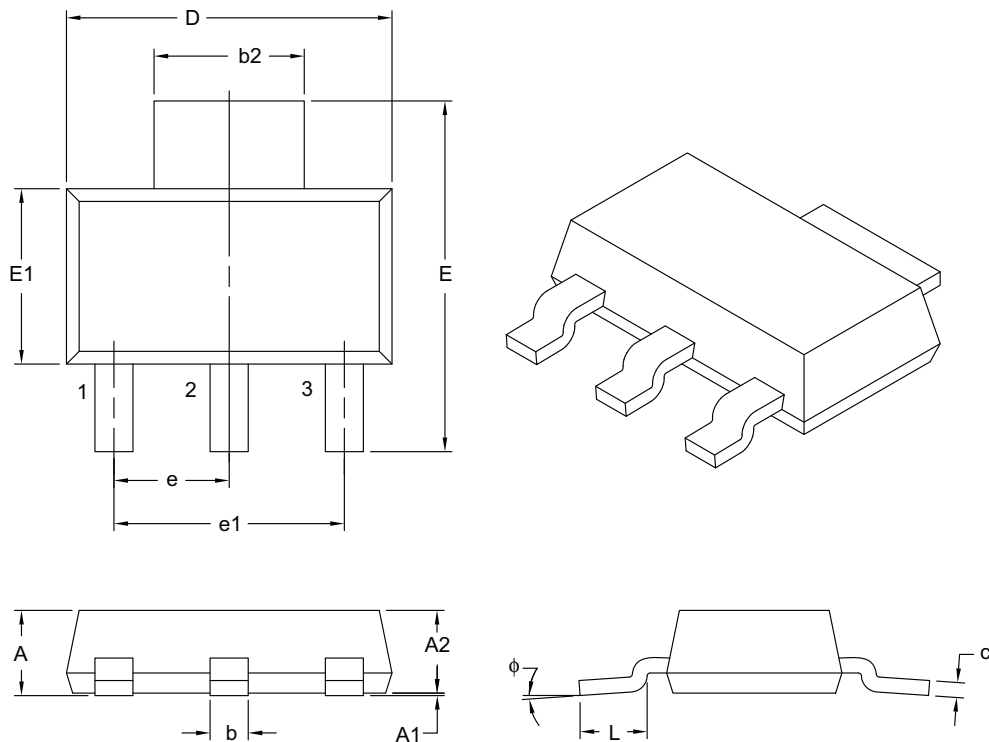
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2011A

MCP1826/MCP1826S

3-Lead Plastic Small Outline Transistor (DB) [SOT-223]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|-----------------------|----|-------|-------------|------|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Leads | N | | 3 | | |
| Lead Pitch | e | | 2.30 BSC | | |
| Outside Lead Pitch | e1 | | 4.60 BSC | | |
| Overall Height | A | | – | – | 1.80 |
| Standoff | A1 | | 0.02 | – | 0.10 |
| Molded Package Height | A2 | | 1.50 | 1.60 | 1.70 |
| Overall Width | E | | 6.70 | 7.00 | 7.30 |
| Molded Package Width | E1 | | 3.30 | 3.50 | 3.70 |
| Overall Length | D | | 6.30 | 6.50 | 6.70 |
| Lead Thickness | c | | 0.23 | 0.30 | 0.35 |
| Lead Width | b | | 0.60 | 0.76 | 0.84 |
| Tab Lead Width | b2 | | 2.90 | 3.00 | 3.10 |
| Foot Length | L | | 0.75 | – | – |
| Lead Angle | φ | | 0° | – | 10° |

Notes:

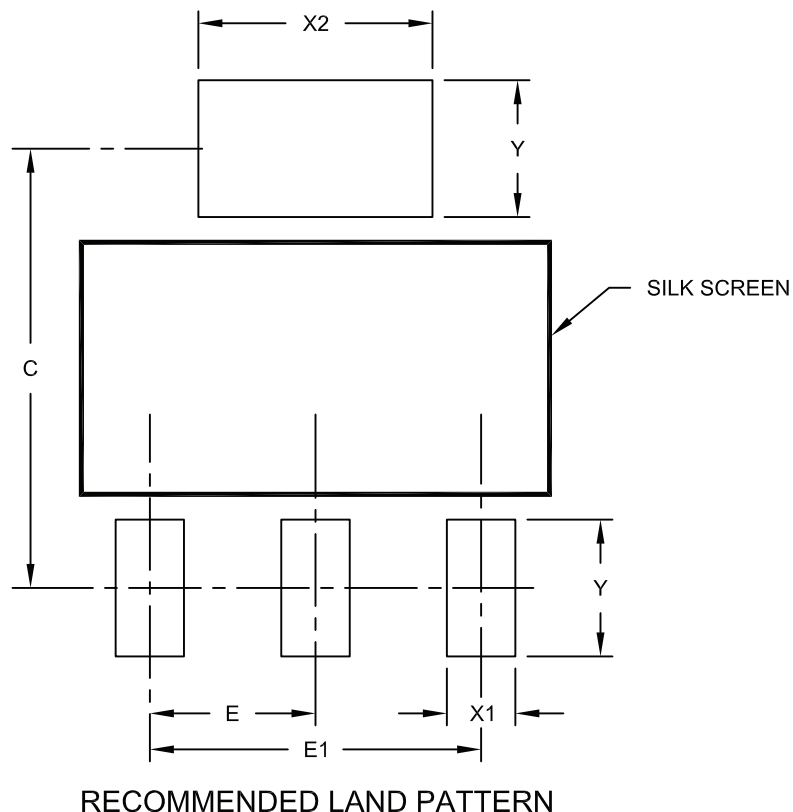
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-032B

3-Lead Plastic Small Outline Transistor (DB) [SOT-223]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



| Dimension Limits | Units | MILLIMETERS | | |
|---------------------|-------|-------------|----------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | | 2.30 BSC | |
| Overall Pitch | E1 | | 4.60 BSC | |
| Contact Pad Spacing | C | | 6.10 | |
| Contact Pad Width | X1 | | | 0.95 |
| Contact Pad Width | X2 | | | 3.25 |
| Contact Pad Length | Y | | | 1.90 |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

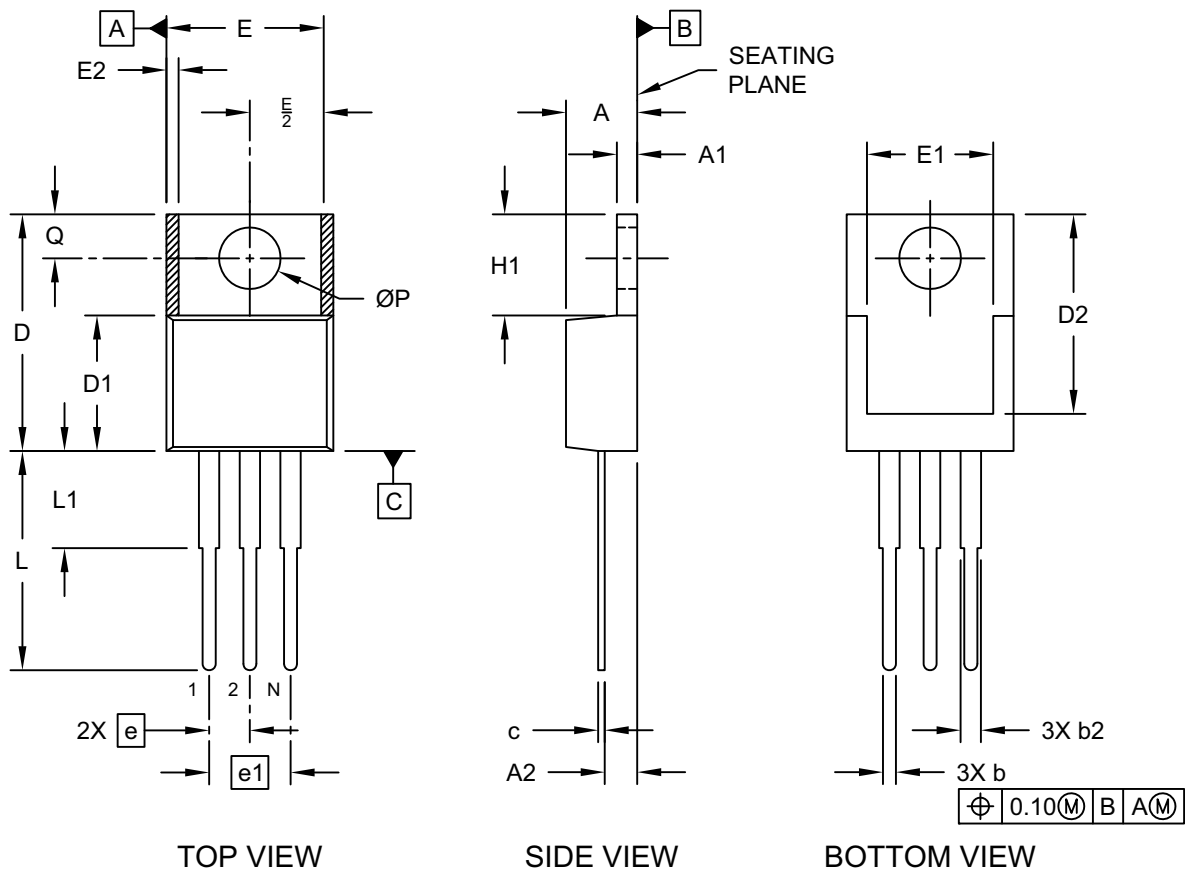
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2032A

MCP1826/MCP1826S

3-Lead Transistor Outline Package (AB) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

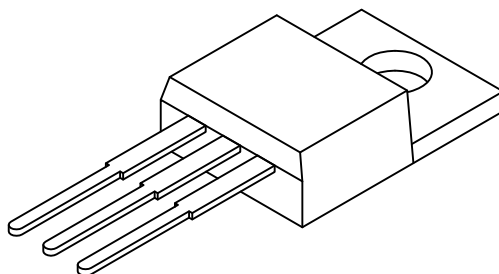


Microchip Technology Drawing C04-034-AB Rev B Sheet 1 of 2

MCP1826/MCP1826S

3-Lead Transistor Outline Package (AB) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | INCHES | | |
|--|----|------------------|----------|------|------|
| | | Dimension Limits | MIN | NOM | MAX |
| Number of Terminals | N | | 3 | | |
| Terminal Pitch | e | | .100 BSC | | |
| Overall Terminal Pitch | e1 | | .200 BSC | | |
| Overall Height | A | | .160 | - | .190 |
| Tab Thickness | A1 | | .045 | - | .055 |
| Base to Lead | A2 | | .090 | - | .115 |
| Terminal Width | b | | .025 | .033 | .040 |
| Shoulder Width | b2 | | .045 | - | .060 |
| Terminal Thickness | c | | .015 | - | .022 |
| Overall Length | D | | .560 | - | .590 |
| Molded Package Length | D1 | | .330 | - | .355 |
| Exposed Pad Length | D2 | | .474 | - | .507 |
| Overall Width | E | | .385 | - | .415 |
| Exposed Pad Width | E1 | | .300 REF | | |
| Allowable Stamping Irregularities Zone | E2 | | - | - | .030 |
| Tab Length | H1 | | .234 | - | .258 |
| Terminal Length | L | | .540 | - | .560 |
| Terminal Shoulder Length | L1 | | .243 REF | | |
| Mounting Hole Diameter | ØP | | .146 | - | .156 |
| Mounting Hole Center | Q | | .103 | - | .113 |

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

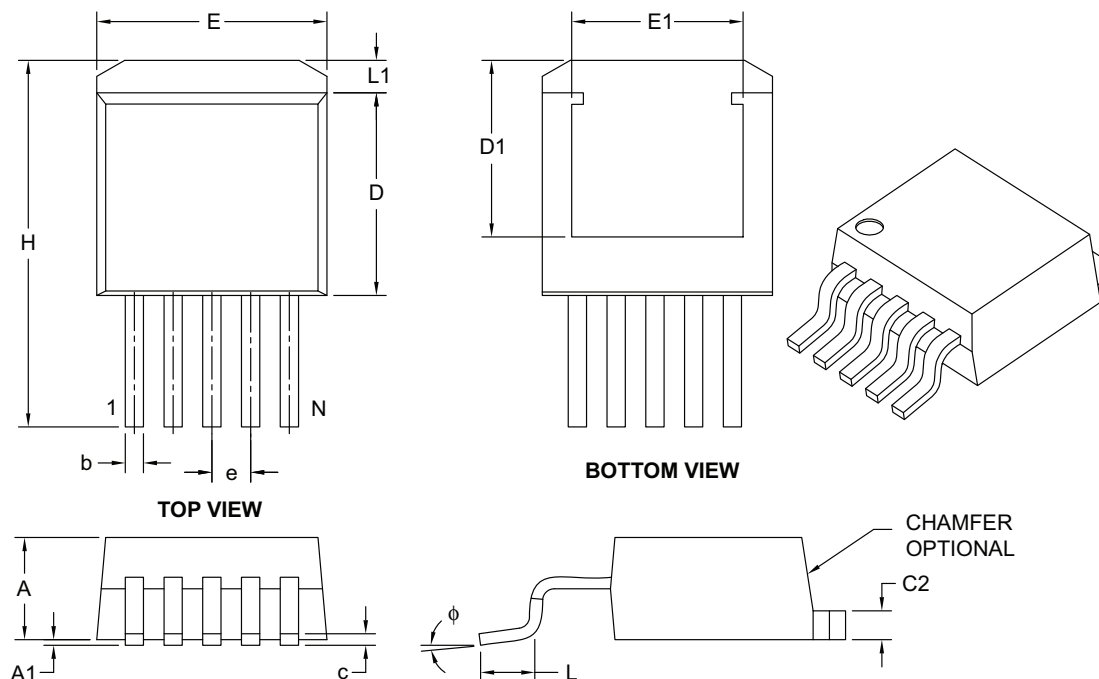
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-034-AB Rev B Sheet 2 of 2

MCP1826/MCP1826S

5-Lead Plastic (ET) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | INCHES | | |
|-----------------------|----|-------|----------|-----|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Pins | N | | 5 | | |
| Pitch | e | | .067 BSC | | |
| Overall Height | A | | .160 | — | .190 |
| Standoff § | A1 | | .000 | — | .010 |
| Overall Width | E | | .380 | — | .420 |
| Exposed Pad Width | E1 | | .245 | — | — |
| Molded Package Length | D | | .330 | — | .380 |
| Overall Length | H | | .549 | — | .625 |
| Exposed Pad Length | D1 | | .270 | — | — |
| Lead Thickness | c | | .014 | — | .029 |
| Pad Thickness | C2 | | .045 | — | .065 |
| Lead Width | b | | .020 | — | .039 |
| Foot Length | L | | .068 | — | .110 |
| Pad Length | L1 | | — | — | .067 |
| Foot Angle | φ | | 0° | — | 8° |

Notes:

- § Significant Characteristic.
- Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

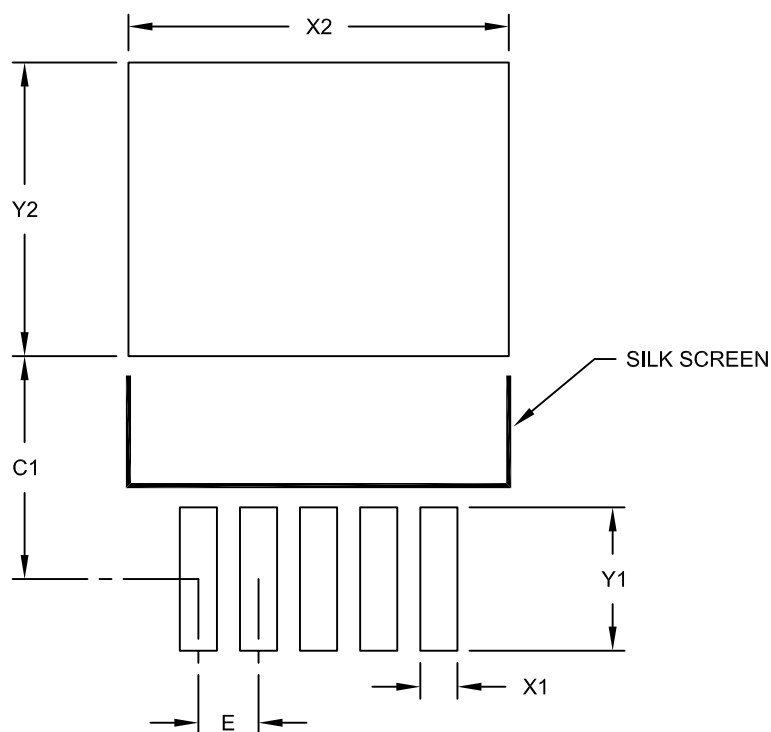
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-012B

MCP1826/MCP1826S

5-Lead Plastic (ET) [DDPAK]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Units | | INCHES | | |
|----------------------------|----|----------|------|------|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | .067 BSC | | |
| Optional Center Pad Width | X2 | | | .423 |
| Optional Center Pad Length | Y2 | | | .327 |
| Contact Pad Spacing | C1 | | .248 | |
| Contact Pad Width (X5) | X1 | | | .041 |
| Contact Pad Length (X5) | Y1 | | | .159 |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

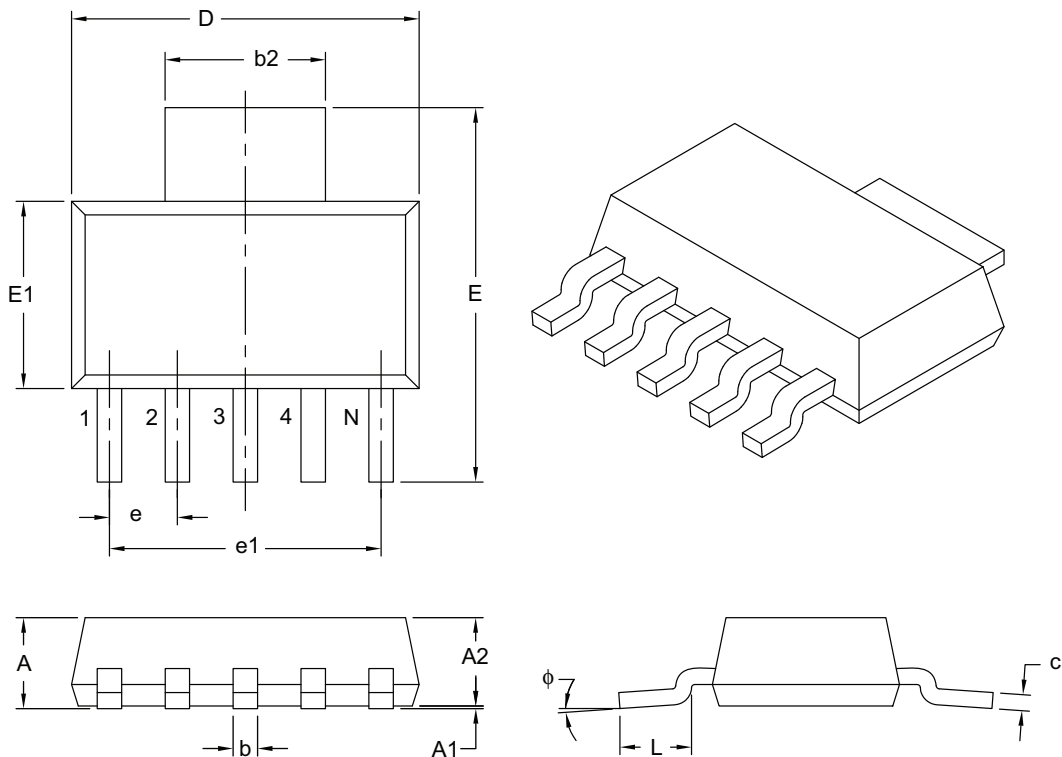
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2012A

MCP1826/MCP1826S

5-Lead Plastic Small Outline Transistor (DC) [SOT-223]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|-----------------------|----|-------|-------------|-------|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Leads | N | | 5 | | |
| Lead Pitch | e | | 1.27 BSC | | |
| Outside Lead Pitch | e1 | | 5.08 BSC | | |
| Overall Height | A | | — | — | 1.80 |
| Standoff | A1 | | 0.02 | 0.06 | 0.10 |
| Molded Package Height | A2 | | 1.55 | 1.60 | 1.65 |
| Overall Width | E | | 6.86 | 7.00 | 7.26 |
| Molded Package Width | E1 | | 3.45 | 3.50 | 3.55 |
| Overall Length | D | | 6.45 | 6.50 | 6.55 |
| Lead Thickness | c | | 0.24 | 0.28 | 0.32 |
| Lead Width | b | | 0.41 | 0.457 | 0.51 |
| Tab Lead Width | b2 | | 2.95 | 3.00 | 3.05 |
| Foot Length | L | | 0.91 | — | 1.14 |
| Lead Angle | φ | | 0° | 4° | 8° |

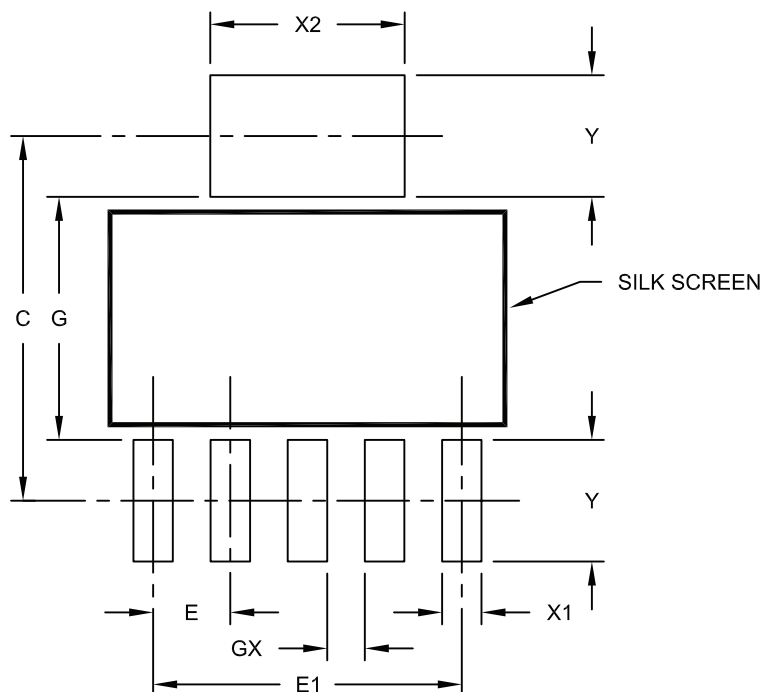
Notes:

- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
 - 2. Dimensioning and tolerancing per ASME Y14.5M.
- BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-137B

5-Lead Plastic Small Outline Transistor (DC) [SOT-223]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|-----------------------|----|-------------|------|------|
| Dimension Limits | | MIN | NOM | MAX |
| Pad Pitch | E | 1.27 BSC | | |
| Overall Pad Pitch | E1 | 5.08 BSC | | |
| Pad Spacing | C | | 6.00 | |
| Pad Width | X1 | | | 0.65 |
| Pad Width | X2 | | | 3.20 |
| Pad Length | Y | | | 2.00 |
| Distance Between Pads | G | 4.00 | | |
| Distance Between Pads | GX | 0.62 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

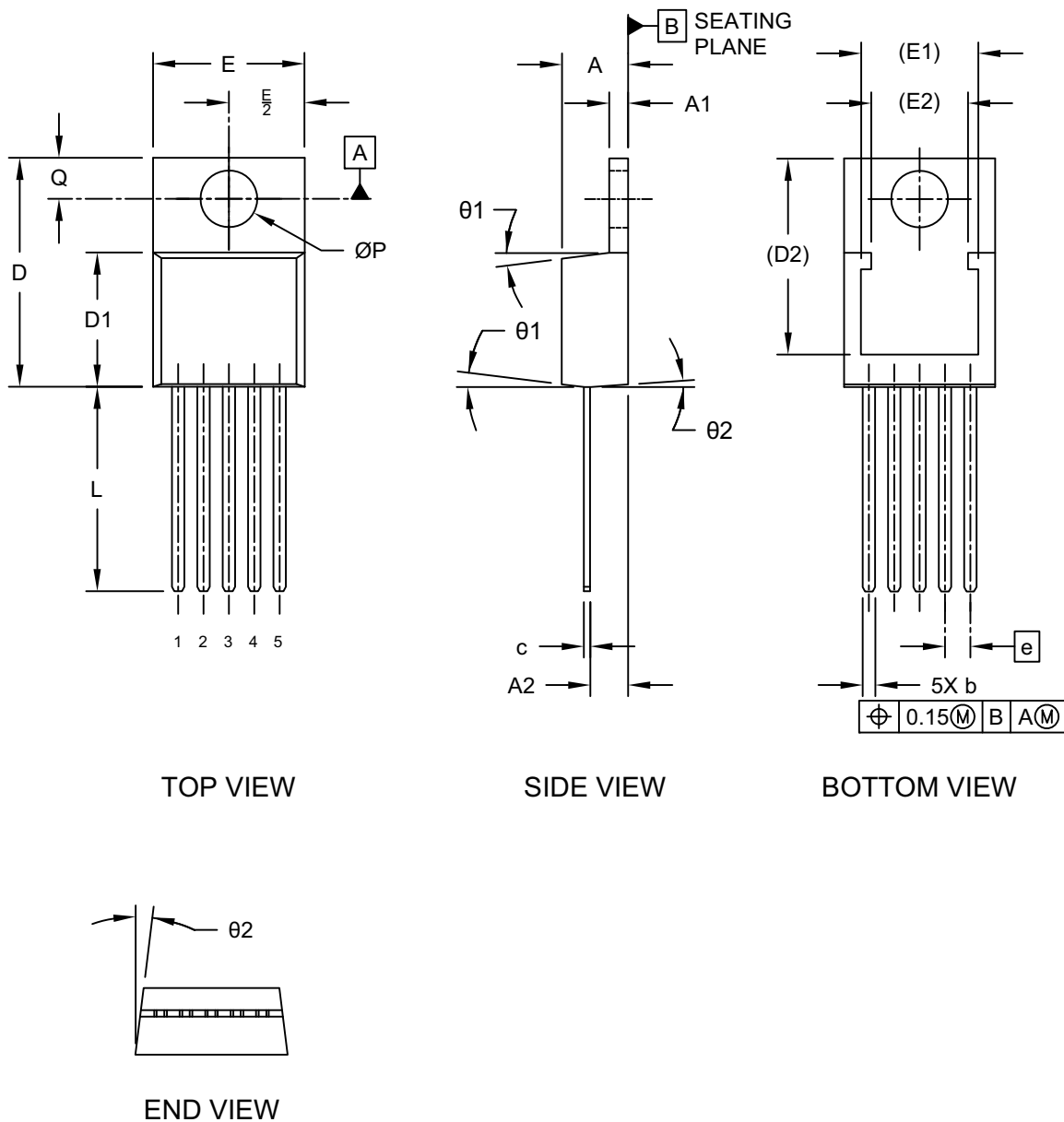
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2137A

MCP1826/MCP1826S

5-Lead Transistor Outline Type LB03 (AT) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

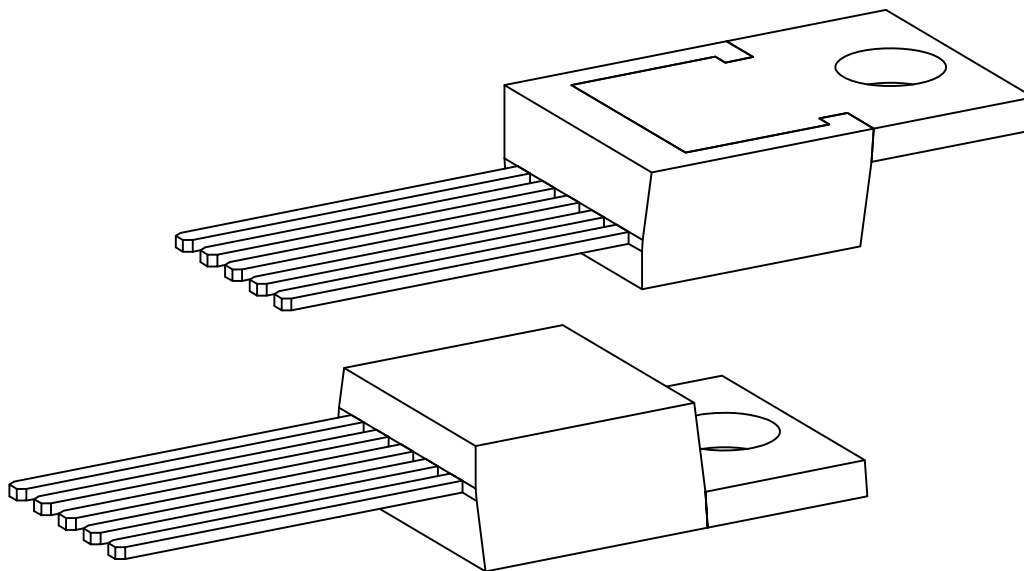


Microchip Technology Drawing C04-036-AT Rev E Sheet 1 of 2

MCP1826/MCP1826S

5-Lead Transistor Outline Type LB03 (AT) - [TO-220]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | INCHES | | |
|---------------------------------|----|-----------|------|------|
| Dimension Limits | | Min | Nom | Max |
| Number of Leads | N | 5 | | |
| Pitch | e | .067 BSC | | |
| Overall Height | A | .160 | .175 | .190 |
| Tab Height | A1 | .045 | .050 | .055 |
| Seating Plane to Lead | A2 | .080 | .098 | .115 |
| Lead Width | b | .025 | .033 | .040 |
| Lead Thickness | c | .012 | .016 | .020 |
| Lead Length | L | .500 | .540 | .580 |
| Total Body Length Including Tab | D | .542 | .580 | .619 |
| Molded Body Length | D1 | .348 | .354 | .360 |
| Total Width | E | .380 | .400 | .420 |
| Pad Width | E1 | 0.256 REF | | |
| Pad Length | D2 | 0.486 REF | | |
| Hole Diameter | ØP | .146 | .151 | .156 |
| Hole Center to Tab Edge | Q | .103 | .108 | .113 |
| Molded Body Draft Angle | Ø1 | 3 | 7 | 10 |
| Molded Body Draft Angle | Ø2 | 1 | 4 | 7 |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-036-AT Rev E Sheet 2 of 2

MCP1826/MCP1826S

NOTES:

APPENDIX A: REVISION HISTORY

Revision C (May 2021)

- Updated the [Features](#) section.
- Updated [Section 6.0 “Packaging Information”](#).
- Updated the [Product Identification System](#) section to include Automotive representation.
- Minor editorial corrections.

Revision B (February 2013)

- Updated the value of $V_{\text{DROPOUT (max)}}$ in [Section 5.1 “Typical Application”](#).

Revision A (August 2007)

- Original Release of this Document.

MCP1826/MCP1826S

NOTES:

MCP1826/MCP1826S

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u> | <u>XX</u> | <u>X</u> | <u>X</u> | <u>X/</u> | <u>XX</u> |
|---|----------------|--------------|-----------|-----------|-----------|
| Device | Output Voltage | Feature Code | Tolerance | Temp. | Package |
| Device: MCP1826: 1000 mA Low Dropout Regulator MCP1826T: 1000 mA Low Dropout Regulator Tape and Reel MCP1826S: 1000 mA Low Dropout Regulator MCP1826ST: 1000 mA Low Dropout Regulator Tape and Reel | | | | | |
| Output Voltage *: 08 = 0.8V "Standard" 12 = 1.2V "Standard" 18 = 1.8V "Standard" 25 = 2.5V "Standard" 30 = 3.0V "Standard" 33 = 3.3V "Standard" 50 = 5.0V "Standard" ADJ = Adjustable Output Voltage ** (MCP1826 only) *Contact factory for other output voltage options ** When ADJ is used, the "extra feature code" and "tolerance" columns do not apply. Refer to examples. | | | | | |
| Extra Feature Code: 0 = Fixed | | | | | |
| Tolerance: 2 = 2.0% (Standard) | | | | | |
| Temperature: E = -40°C to +125°C | | | | | |
| Package Type: AB = Plastic Transistor Outline, TO-220, 3-lead AT = Plastic Transistor Outline, TO-220, 5-lead DB = Plastic Transistor Outline, SOT-223, 3-lead DBVAO= Plastic Transistor Outline, SOT-223, 3-lead, Automotive DC = Plastic Transistor Outline, SOT-223, 5-lead EB = Plastic, DDPACK, 3-lead ET = Plastic, DDPACK, 5-lead Note: ADJ (Adjustable) only available in 5-lead version. | | | | | |
| Examples: a) MCP1826-0802E/XX: 0.8V LDO Regulator b) MCP1826-1002E/XX: 1.0V LDO Regulator c) MCP1826-1202E/XX: 1.2V LDO Regulator d) MCP1826-1802E/XX: 1.8V LDO Regulator e) MCP1826-2502E/XX: 2.5V LDO Regulator f) MCP1826-3002E/XX: 3.0V LDO Regulator g) MCP1826-3302E/XX: 3.3V LDO Regulator h) MCP1826-5002E/XX: 5.0V LDO Regulator i) MCP1826-ADJE/XX: ADJ LDO Regulator a) MCP1826S-0802E/XX: 0.8V LDO Regulator b) MCP1826S-1002E/XX: 1.0V LDO Regulator c) MCP1826S-1202E/XX: 1.2V LDO Regulator d) MCP1826S-1802E/XX: 1.8V LDO Regulator e) MCP1826S-2502E/XX: 2.5V LDO Regulator f) MCP1826S-3002E/XX: 3.0V LDO Regulator g) MCP1826S-3302E/XX: 3.3V LDO Regulator h) MCP1826S-5002E/XX: 5.0V LDO Regulator XX = AB for 3LD TO-220 package = AT for 5LD TO-220 package = DB for 3LD SOT-223 package = DBVAO for 3LD SOT-223 package, Automotive = DC for 5LD SOT-223 package = EB for 3LD DDPACK package = ET for 5LD DDPACK package | | | | | |

MCP1826/MCP1826S

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
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- There are dishonest and possibly illegal methods being used in attempts to breach the code protection features of the Microchip devices. We believe that these methods require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Attempts to breach these code protection features, most likely, cannot be accomplished without violating Microchip's intellectual property rights.
- Microchip is willing to work with any customer who is concerned about the integrity of its code.
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